SIDDAGANGA INSTITUTE OF TECHNOLOGY, TUMAKURU 572103, KARNATAKA, INDIA

DEPARTMENT OF ELECTRONICS AND INSTRUMENTATION ENGINEERING



SCHEME & SYLLABUS

OF

PG Course on

VLSI Design and Embedded Systems

2023-24

Department of E&IE, SIT, Tumakuru

SIDDAGANGA INSTITUTE OF TECHNOLOGY, TUMAKURU-03

(An autonomous Institute under Visvesvaraya Technological University)

SCHEME OF TEACHING AND EXAMINATION

I SEMESTER M.Tech. VLSI Design and Embedded Systems

	Sl. Course Type and No. Course Code			Teac	hing Hours	s per Week	Examination				
S1. No.			Course Title		Practical / Seminar	Tutorial / Skill Development Activities	Duration in hrs.	CIE Marks	SEE Marks	Total Marks	Credits
				L	Г	IJSDA					
1.	BSC	N1LVSMAT	Applied Mathematics	3	0	0	3	50	50	100	3
2.	IPCC	N1LVSI01	VLSI Design	3	2	0	3	50	50	100	4
3.	PCC	N1LVS02	Analog IC Design	3	0	2	3	50	50	100	4
4.	PCC	N1LVS03	ARM Microcontroller and its Applications	2	0	2	3	50	50	100	3
5.	PCC	N1LVS04	Digital System Design Using Verilog	2	0	2	3	50	50	100	3
6.	PEC	N1LVSE1x	Professional Elective – 1	2	-	2	3	50	50	100	3
7.	MCC	N1PGRM	Research Methodology and IPR	3	0	0	3	50	50	100	3
8.	PCCL	N1LVSL1	Embedded Systems Lab	1	2	0	3	50	50	100	2
9.	AUD/ AEC	N1LVSAUD / N1LVSAEC	BoS Recommended online course	Classe	es and E	valuation F of the online	Procedur e course	es are a provide	s per the	e policy	0
			Total	19	4	8		500	400	900	25
			Professional Elec	tive 1			I				
	N1L	VSE11	ASIC Design	N1L	VSE13		VLS	SI for Dig	gital Sig	nal Proc	essing
	N1L	VSE12	VLSI Design Automation	N1LVSE14 Nano Electronic			ronics				

Note: BSC-Basic Science Courses, IPCC-Integrated Professional Core Courses, PCC: Professional Core Course, PEC: Professional Elective Course, MCC- Mandatory Credit Course, PCL-Professional Core Course Lab, NCMC-Non Credit Mandatory Course
 AUD/AEC –Audit Course / Ability Enhancement Course(A pass in AUD/AEC is mandatory for the award of the degree)
 L-Lecture, P-Practical, T/SDA-Tutorial / Skill Development Activities (Hours are for Interaction between faculty and students)

Integrated Professional Core Course (IPCC): Refers to Professional Theory Core Course Integrated with practical of the same course. The theory part of the IPCC shall be evaluated both by CIE and SEE. The practical part shall be evaluated by only CIE (no SEE). However, questions from the practical part of IPCC shall be included in the SEE question paper.

Audit Courses /Ability Enhancement Courses suggested by BoS (ONLINE courses):

Audit Courses are prerequisite courses suggested by the concerned Board of Studies.

Ability Enhancement Courses will be suggested by the BoS if prerequisite courses are not required for the programs.

- These courses are prescribed to help students to enhance their skills connected to the field of specialization as well allied fields that leads to employable skills. Involving in learning such courses are impetus to lifelong learning.
- The courses under this category are online courses published in advance and approved by the concerned Board of Studies.
- Registration to Audit /Ability Enhancement Course shall be done in consultation with the mentor and is compulsory during the concerned semester.
- In case a candidate fails to appear for the proctored examination or fails to pass the selected online course, he/she can register and appear for the same course if offered during the next session or register for a new course offered during that session, in consultation with the mentor.

The Audit / Ability Enhancement Course carries no credit and is not counted for vertical progression. However, a pass in such a course is mandatory for the award of the degree.

Skill development activities: in a concerned course, the students should

- Interact with industry (small, medium, and large).
- Involve in research/testing/projects to understand their problems and help creative and innovative methods to solve the problem.
- Involve in case studies and field visits/ fieldwork.
- Accustom to the use of standards/codes etc., to narrow the gap between academia and industry.
- Handle advanced instruments to enhance technical talent.
- Gain confidence in modelling of systems and algorithms for transient and steady-state operations, thermal study, etc.
- Work on different software to simulate, analyze and authenticate the output to interpret and conclude.

All activities should enhance student's abilities to employment and/or self-employment opportunities, management skills, Statistical analysis, fiscal expertise, etc. Students and the course instructor/s to involve either individually or in groups to interact together to enhance the learning and application skills of the study they have undertaken. The students with the help of the course teacher can take up relevant technical – activities which will enhance their skill. The prepared report shall be evaluated for CIE marks.

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SCHEME OF TEACHING AND EXAMINATION

II SEMESTER M.Tech. VLSI Design and Embedded Systems

				Teacl	hing Hours	per Week	Examination				Credits
S1. No.	Cou	urse Type and course Code	Course Title T		Practical / Seminar P	Tutorial / Skill Development Activities T/SDA	Duration in hrs.	CIE Marks	SEE Marks	Total Marks	
1.	IPCC	N2LVSI01	Real time operating systems	3	2	0	3	50	50	100	4
2.	PCC	N2LVS02	VLSI Process Technology	3	3 0 2		3	50	50	100	4
3.	PCC	N2LVS03	Design of IoT Systems	2	0	2	3	50	50	100	3
4.	PEC	N2LVSE2x	Professional Elective – 2	2	0	2	3	50	50	100	3
5.	PEC	N2LVSE3x	Professional Elective – 3	2	0	2	3	50	50	100	3
6.	PEC	N2LVSE4x	Professional Elective 4	2	0	2	3	50	50	100	3
7.	MPS	N2LVSMPS	Mini Project with Seminar	0	4	2		100		100	3
8.	PCCL	N2LVSL1	VLSI Design Lab	1	2	0	3	50	50	100	2
9.	AEC	ARAS	Aptitude Related Analytical Skills	36 H	36 Hrs. for the entire semester		2	50	50	100	0
10	AUD/ AEC	N2LVSAUD / N2LVSAEC	C BoS Recommended online course		Classes and Evaluation I of the online		Procedures are as per the policy le course providers			0	
			Total	15	8	12		500	400	900	25

Note: IPCC-Integrated Professional Core Courses, PCC: Professional Core Course, PEC: Professional Elective Course, OEC- Open Elective Course
 MPS- Mini Project with Seminar, PCCL-Professional Core Course Lab, AUD/AEC –Audit Course / Ability Enhancement Course (A pass in AUD/AEC is mandatory for the award of the degree) L-Lecture, P-Practical, T/SDA-Tutorial / Skill Development Activities (Hours are for Interaction between faculty and students)

Professiona	al Elective 2	Professiona	al Elective 3	Professional Elective 4			
N2LVSE21	CMOS RF Circuit Design	N2LVSE31	System on Chip (SoC) Design	N2LVSE41	DSP Architecture		
N2LVSE22	Mixed Signal Circuit Design	N2LVSE32	System Verilog	N2LVSE42	Wireless sensor network		
N2LVSE23	VLSI Testing and Verification	N2LVSE33	Low power VLSI Design.	N2LVSE43	Data Structures using C		
N2LVSE24	Design of CMOS Phase Locked Loops	N2LVSE34	Interface and Noise control technique in Electronic System design	N2LVSE44	RISC V Processor Design		

Mini Project with Seminar: This may be hands-on practice, survey report, data collection and analysis, coding, mobile app development, field visit and report preparation, modelling of system, simulation, analysing and authenticating, case studies, etc.
 CIE marks shall be awarded by a committee comprising of HoD as Chairman, Guide/co-guide, if any, and a senior faculty of the department. Students can present the seminar based on the completed mini-project. Participation in the seminar by all postgraduate students of the program shall be mandatory.

The CIE marks awarded for Mini-Project work and Seminar, shall be based on the evaluation of Mini Project work and Report, Presentation skill and performance in Question and Answer session in the ratio 50:25:25. Mini-Project with Seminar shall be considered as a head of passing and shall be considered for vertical progression as well as for the award of degree. Those, who do not take-up/complete the Mini Project and Seminar shall be declared as fail in that course and have to complete the same during the subsequent semester. **There is no SEE for this course.**

2. Internship: All the students shall have to undergo a mandatory internship of **06 weeks** during the vacation of II and III semesters. A University examination shall be conducted during III semester and the prescribed internship credit shall be counted in the same semester. The internship shall be considered as a head of passing and shall be considered for vertical progression as well as for the award of degree. Those, who do not take-up/complete the internship shall be declared as fail in the internship course and have to complete the same during the subsequent University examination after satisfying the internship requirements.

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SCHEME OF TEACHING AND EXAMINATION

III SEMESTER M.Tech. VLSI Design and Embedded Systems

		Teaching Hours per Week Examination									
S1. No.	Cou C	urse Type and ourse Code	Course Title	Theory	Practical / Seminar	Tutorial / Skill Development Activities	Duration in hrs.	CIE Marks	SEE Marks	Total Marks	Credits
				L	Р	T/SDA					
1.	PROJ	N3LVSPR	Project Work Phase – 1	0	6	0		100		100	3
2.	SP	N3LVSSP	Societal Project	0	6	0		100		100	3
3.	3. INT N3LVSINT Internship				5 weeks mpleted tervenin I and III	Internship during the ng vacation semesters)	3	50	50	100	6
	Total 0 12 0 250 50 300							12			
1. 2. 3.	Project V not more Students survey an CIE mark for projec is no SEI Societal 1 for societal CIE mark evaluation Those, wl Societal F Internshi examinat CIE mark -1, shall l	Vork Phase-1: The than three shall be in consultation with ad complete the pre- as shall be awarded t work phase -1, she Froject: Students i al problems. The shall be awarded in of Project Report, he have not pursue Project requirement ip: Those, who have ions after satisfying as shall be awarded be based on the eval	project work shall be carried out individually. However, in case a cepermitted. the guide/co-guide (if any) in disciplinary project or guides/co-guide diminary requirements of the selected Project work. Each student by a committee comprising of HoD as Chairman, all Guide/s and hall be based on the evaluation of Project Report, Project Presentation n consultation with the internal guide as well as with external guide by a committee comprising of HoD as Chairman, Guide/co-guide Project Presentation skill, and performance in the Question and A ed /completed the Societal Project, shall be declared as fail in the s. There is no SEE for this course . we not pursued /completed the internship, shall be declared as g the internship requirements. Internship SEE (University examin- by a committee comprising of HoD as Chairman, Guide/co-guide a g the internship requirements. Internship SEE (University examin- by a committee comprising of HoD as Chairman, Guide/co-guide a g the internship requirements. Internship SEE (University examin- by a committee comprising of HoD as Chairman, Guide/co-guide a g the internship requirements. Internship SEE (University examin- by a committee comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for the comprising of HoD as Chairman, Guide/co-guide a guarded for th	disciplina guides (if a shall prep co-guide/ ion skill, a le (much p if any, an Answer se he course fail in the ation) sha if any, an unce in the	ry or inter any) of all pare a rele s (if any) a and perfor preferable) d a senior ssion in t and have e internsh ll be as per d a senior e Questior	departments in case want introductory p and a senior faculty mance in the Ques shall involve in app r faculty of the depa he ratio of 50:25:25 to complete the sa hip course and hav er the University no faculty of the depa and Answer session	e of multid project doct of the cond tion and Ar olying tech: artment. Th ame during e to complor orms. urtment. Th on in the ra	y and st nore parti isciplinary ument, an cerned dep nswer sess nology to v ne CIE ma g subseque lete the sa the CIE man atio of 50::	cipants, ti y projects, id present partments sion in the workout/p rks award ent semes ame durin rks award 25:25.	nen a grou shall purs a seminar The CIE n ratio of 50 roposing v ed, shall b ter/s after g subsequ ed for proje	p consisting of ue a literature marks awarded 0:25:25. There iable solutions e based on the satisfying the ent University ect work phase

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SCHEME OF TEACHING AND EXAMINATION

IV SEMESTER M.Tech. VLSI Design and Embedded Systems

				Teac	hing Hours	per Week		Exami	nation		
S1. No.	Sl. Course Type and No. Course Code		Course Type and Course Title Course Code		Practical / Field work	Tutorial / Skill Development Activities	Duration in hrs.	CIE Marks	SEE Marks	Total Marks	Credits
				L	Р	T/SDA					
1.	PROJ	N4LVSPR	Project Work Phase – 2	0	36	0	3	100	100	100	18
	Total				36	0		100	100	100	18

Note: **PROJ**-Project Work Phase-2, **L**-Lecture, **P**-Practical, **T/SDA**-Tutorial / Skill Development Activities (Hours are for Interaction between faculty and students)

1. **Project Work Phase-2:** Students in consultation with the guide/co-guide (if any) in disciplinary project or guides/co-guides (if any) of all departments in case of multidisciplinary projects, shall continue to work of Project Work phase -1to complete the Project work. Each student / batch of students shall prepare project document, and present a seminar.

CIE marks shall be awarded by a committee comprising of HoD as Chairman, all Guide/s and co-guide/s (if any) and a senior faculty of the concerned departments. The CIE marks awarded for project work phase -2, shall be based on the evaluation of Project Report, Project Presentation skill, and performance in the Question and Answer session in the ratio of 50:25:25.

SEE shall be at the end of IV semester. Project work evaluation and Viva-Voce examination (SEE), after satisfying the plagiarism check, shall be as per the Institute norms.

Subject	Weeks
Nanotechnology, Science and Applications	8 Weeks
VLSI Interconnects	8 Weeks
Multi-Core Computer Architecture - Storage and Interconnects	8 Weeks
Robotics	8 Weeks
Introduction To Machine Learning - KGP	8 Weeks
Introduction to Industry 4.0 and Industrial Internet of Things	8 Weeks
Introduction to Machine Learning	8 Weeks
Programming, Data Structures and Algorithms Using Python	

ACADEMIC YEAR: 2023-24 APPLIED MATHEMATICS

Contact Hours/ Week	: 4	Credits :	4.0
Total Lecture Hours	: 50	CIE Marks :	50
Lab work	:	SEE Marks :	50
Sub. Code	: N1LVSMAT		

UNIT- I

Numerical Methods: Solution of algebraic and transcendental equations iterative methods based on second degree equation _ Muller method, (noderivation) Chebyshev method, general iteration method (first order), acceleration of convergence, system of non-linear equations, and complex roots - Newton-Raphson method, polynomial equations - Birge -Vieta method and Bairstow's method. Interpolation: Hermite interpolation, spline interpolation, numerical solution of differential equations - Numerov method. 10 Hrs

UNIT- II

Numerical Solution of Partial Differential Equations: Classification of second order equations, parabolic equations- solution of one dimensional heat equation, explicit method, Crank-Nicolson method and Du Fort-Frankel method, hyperbolic equations- solution of one dimensional wave equation.

10 Hrs

UNIT- III

System of Linear Algebraic Equations and Eigen Value Problems:

Iterative methods - Gauss-Seidal method, SOR method, Eigen value problems – Gerschgorian circle, Eigen values and Eigen vectors of real symmetric matrices -Jacobi method, Givens method.

10 Hrs

UNIT- IV

Optimization: **Linear programming**- formulation of the problem, graphical method, general linear programming problem, simplex method, artificial variable technique - M-method.

10 Hrs

UNIT- V

Optimization: Nonlinear programming: single variable optimization-local and global optima, searching techniques, convex functions. Multivariable optimization without constraints-local and global maxima, Gradient vector and Hessian matrix, the method of steepest ascent, Newton-Raphson method, Fletcher-powell method, searching techniques, choice of an initial approximation, concave function. Multivariable optimization with constraints-standard forms, Lagrange multipliers, Newton Raphson method,

penalty functions, Kuhn-Tucker conditions, method of feasible directions.

Reference Books:

M K Jain, S R K Iyengar and R K	Numerical Methods for Scientific and Engineering Computations, 6 th Edition, New Age International,					
Jain	2004.					
M K Join	Numerical Solution of Differential Equations, 2 nd					
W K Jaili	Edition, New Age International, 2008.					
Dr. B.S. Grewal	Numerical Methods in Engineering and Science, Khanna Publishers, 2012.					
Dr. B.S. Grewal	Higher Engineering Mathematics, 43 rd Edition, Khanna Publishers, 2015.					
Richard Bronson and Govindasami Naadimuthu	Schaum's out lines Operations Research, 2 nd edition, Tata McGraw-Hill Publishers, 1997.					
Kenneth Hoffman and Ray Kunze	Linear Algebra, 2nd Edition, PHI, 2011.					

VLSI Design

Contact Hours/ Week	:3+2+0(L+P+T)	Credits :	4.0
Total Lecture Hours	: 40	CIE Marks :	50
Total Lab Hours	: 26	SEE Marks :	50
Course Code	: N1LVSI01		

Course Objective: This course enables the students to analyze and design combinational, sequential, memory and BiCMOS circuits.

UNIT- I

Introduction: MOS Structure, MOS system under External Bias, Structure and operation of the MOSFET, MOSFET Current-Voltage Characteristics, MOSFET Capacitance.

MOS Inverters- StaticCharacteristics:Introduction,Resistive-LoadInverter.08 Hrs

UNIT- II

Combinational Logic Circuits: Static CMOS inverter, Static behaviour, Propagation delay, Power dissipation, Pseudo NMOS inverter, Static CMOS design, Pass gates, CMOS Transmission Gates, Dynamic CMOS design.

08 Hrs

UNIT- III

Sequential Logic Circuits: Timing metrics for sequential circuits, Static latches and Registers: The Bi-stability principle, Multiplexer based Latches, Master slave edge triggered registers, Static SR Flip-Flops. Dynamic Latches

and Registers: Dynamic Transmission gate Edge triggered registers, C²MOS, True Single Phase Clock Registers (TSPCR).

08 Hrs

UNIT- IV

Arithmetic Building blocks: Adders, Multipliers, Barrel shifter.

Semiconductor Memories:Memory Classification, Non-VolatileMemorydevices.Read-Only Memory (ROM) Circuits,08 Hrs

UNIT- V

Semiconductor Memories contd.. : Static Read-Write Memory (SRAM) Circuits, Dynamic Read-Write Memory (DRAM) Circuits

BiCMOS Logic Circuits: Introduction, Basic BiCMOS Circuits: Static Behavior, Switching Delay in BiCMOS Logic Circuits, BiCMOS Applications.

Chip Input and Output (I/O) Circuits: Introduction, ESD Protection, Input Circuits, Output Circuits and L (di/dt) Noise, On-Chip Clock Generation and Distribution. 08 Hrs

Text Books:

1	Jan	Μ	Raba	ey,	Digital Integrated Circuit A Design Perspective	э,
	Anant	ha			2 nd Edition, PHI, 2016.	
	Chandrakasan,					
	Borivo	je Nil	colic			
2	Sung	Mo	Kang	&	CMOS Digital Integrated Circuits: Analysis an	d
	Yosufl	Leblet	oici,		Design, 41 th Edition, Tata McGraw-Hill, 2002	

Reference Books:

1	Neil Weste and K.	Principles of CMOS VLSI Design: A System						
	Eshragian,	Perspective, 2 nd Edition, Pearson Education (Asia)						
		Pvt. Ltd. 2000.						
2	Adel Sedra and	Microelectronic Circuits Theory and Applications						
	Kenneth C. Smith	7 th Edition, Oxford Higher Education, 2017.						

Course Outcomes: students will be able to

CO1: Analyze the MOS structure and inverter characteristics

CO2: Analyze and design combinational circuits with different design styles.

- **CO3:** Analyze and design sequential circuits with different design styles.
- **CO4:** Analyze and design arithmetic building blocks and Non-Volatile Memory cells.
- **CO5:** Analyze and design Volatile Memory circuits, BiCMOS circuits & Chip I/O circuits.
- **CO6:** Design selected circuit for a particular application using Mentor graphics/Cadence. Prepare the report.

Practicals for CIE

- Design and simulate the following circuits using NG-Spice for the given specifications.
- 1. Characterization of NMOS transistor.
- 2. Design the following static CMOS gates
 - a. Inverter
 - b. 2-input NAND
 - c. 2-input NOR
 - d. 2-input XOR
 - e. 2-input XNOR.
 - Design (Schematic and Layout) and simulate the following circuits using Mentor graphics or Cadence for the given specifications.
- 3. Design the following gates using Static CMOS design style, Pass transistor style and Dynamic gates style.
 - a. Inverter
 - b. 2-input NAND
 - c. 2-input NOR
 - d. 2-input XOR
 - e. 2-input XNOR.
- 4. Design a Static CMOS D-register.
- 5. Design a Static CMOS Full Adder.
- 6. Design 32 bit adder using the specified topology.
- 7. Design SRAM.

Analog IC Design

<u> </u>			
Contact Hours/ Week	:3+0+2(L+P+T)	Credits :	4.0
Total Lecture Hours	: 40	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N1LVS02		

Course Objective: To impart the knowledge of Analog CMOS IC design for different amplifier topologies.

UNIT – I

Introduction: Introduction to Analog IC design, General concepts - Levels of abstraction, Robustness in Analog design, MOS structure, MOS under external bias, MOSFET: Structure, Threshold voltage, I/V Characteristics, Capacitance. Small signal model.

(08+05) Hrs

Single stage amplifiers: Common source stage – with resistive load, Diode connected load, current source load, Triode load, Source degeneration. Source follower, Common gate stage, Cascode stage.

UNIT – II

(08+05) Hrs

UNIT – III

Differential amplifiers: Single ended differential operation, Basic differential pair, common mode response, Differential pair with MOS loads, Current mirrors: Basic current mirrors, Cascode current mirrors, Active current mirrors.

(08+05) Hrs

$\mathbf{UNIT} - \mathbf{IV}$

Frequency response of amplifiers: Miller effect, Association of poles with nodes, CS-stage, Source followers, CG-stage. Feedback: General feedback considerations, Feedback topologies. Two port network models.

(08+06) Hrs

$\mathbf{UNIT} - \mathbf{V}$

Operational Amplifier: General considerations, one-stage OP Amps, Two-Stage opamps, Common mode feedback, input range limitations, slew rate, power supply rejection. Stability and Frequency Compensation: General considerations, Multipole systems, Phase margin, Frequency compensation, compensation of two stage op-amps.

(08+05) Hrs

Text Book:

1	Behzad Razavi	Design of Analog CMOS Integrated Circuits 2nd
		Edition, McGraw Hill Education Private Limited,
		2017.

Reference Books:

1	Adel	Sedra	and	Microelectronic Circuits Theory and Applications
	Kennet	h C. Sı	nith	7 th Edition, Oxford Higher Education, 2017.
2	P.R.	Gray;	P.J.	Analysis and Design of Analog Integrated circuits,
	Hurst;	S.H.	Lewis;	5 th Edition, Wiley, 2009.
	R.G. M	eyer		

Course Outcomes: students will be able to

- **CO1:** Analyze the MOS structure and explain the operation of MOSFET.
- **CO2:** Analyze and design single stage CMOS amplifiers with different loads.
- **CO3:** Analyze and design differential amplifiers and current mirrors

with different loads.

- **CO4:** Analyze frequency response of amplifiers and discuss the operation of feedback networks.
- **CO5:** Analyze and design operational amplifiers.

ARM Microcontroller and its Applications

Contact Hours/ Week	: 2+0+2 (L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N1LVS03		

Course Objective: To impart the knowledge of Cortex M3 and M4 based Microcontroller Architecture, Exception and Interrupt behavior, Programming and configuring on chip peripherals and interfacing of I/O devices.

UNIT- I

Introduction: Microprocessors and Microcontrollers, Von-Neumann and Harvard Architectures, History of ARM family of processors, Architecture and Features of ARM Cortex M3 and M4 processors. Programmer's model: Operation Modes and States, General purpose Registers, Special function Registers, Behavior of APSR. Pipelining, Pre-fetch unit and Branch target forwarding in ARM cortex M3 and M4 processors. Memory system: Memory map.

(05+05) Hrs

UNIT- II

Memory Format: Memory endianness, data alignment and unaligned data access support, Bit-band operation in ARM Cortex M3 and M4 processors. Embedded Software development-1: Embedded Software Development and compilation flow. Data types in C – programming used for Cortex M4 processors. Introduction to Cortex M3 based Microcontroller: Features, Memory map, basic configuration and programming of GPIO. Interfacing Input output devices to Cortex M3 based Microcontroller-1: LEDs and Switches, C-Programming examples.

(05+05) Hrs

UNIT- III

Instruction set: Operation and addressing modes of MOV instruction, Arithmetic instructions, Logical instructions, Memory access instructions, Program flow control instructions, Shift and rotate instructions, Data conversion instructions, Bit-field processing instructions, compare and test instructions. Use of suffix in instructions. ARM Assembler directives,

Assembly level programming examples. Interfacing Input output devices to Cortex M3 based Microcontroller-2: 7-segment Display, Push button keys, mxn matrix keypad. Programming examples (Both assembly and C).

(05+05) Hrs

UNIT- IV

Embedded Software development-2: Program flow (Software Flow).

Exceptions and Interrupts: Overview of Exceptions and Interrupts, Exception types, Vector table and Reset status, Exception entrance sequence, Exception handler execution, Exception return, Interrupt latency, NVIC registers for interrupt control, Exception handlers in C and assembly level programming, Stack Frames, Exceptions entrance and stacking, Exception return and unstacking. Programming Examples (Both assembly and C). System control blocks of Cortex M3 and M4 based Microcontroller: Reset, Brown-out detection and External interrupt inputs.

Peripherals in Cortex M3 and M4 based Microcontroller: Configuration and programming (both assembly and C) Nested Vectored Interrupt Controller (NVIC) and Timers.

(05+05) Hrs

UNIT-V

Configuration and programming (Only C) PWM unit, Watchdog timer, Analog to Digital Converter (ADC), Digital to Analog Converter (DAC), Universal Asynchronous Receiver Transmitter (UART), SPI and I2C. Interfacing Input output devices to Cortex M3 and M4 based Microcontroller-3: Stepper Motor, DC motor, Opto-coupler, Relay unit, Programming examples (both assembly and C).

(06+06) Hrs

Text Books:

1	Joseph Yiu The Definitive guide to ARM Cortex M3 and	
		Cortex M4 processor, Elsevier, 3rd Edition, 2013.
2	Cortex-M Technical Reference Manual. revision r1p1	
3	LPC17xx Reference I	Manual.

Reference Book:

1	Ming-Bo Lin	An Introduction to Cortex-M3-Based Embedded
		Systems: Cortex-M3 Assembly Language
		Programming, Createspace Independent
		Publishing Platform, 2019.

Course Outcomes: Students will be able to

- **CO1:** Discuss the architecture of ARM cortex M3 and M4.
- **CO2:** Develop the C-program for ARM cortex M3 and M4 based microcontrollers in order to Interface Input and output devices.
- **CO3:** Develop the Assembly level program for ARM cortex M3 and M4 based microcontrollers in order to Interface Input and output devices.
- **CO4:** Discuss the concept of Exceptions and interrupts, and Develop the program to configure External interrupts, NVIC and Timers of ARM cortex M3 and M4 based microcontrollers.
- **CO5:** Develop the program to configure PWM, ADC, DAC and UART of ARM cortex M3 and M4 based microcontroller.

Digital System Design Using Verilog

: 2+0+2 (L+P+SDA)	Credits :	3.0
: 26	CIE Marks :	50
: 26		
: N1LVS04	SEE Marks :	50
	: 2+0+2 (L+P+SDA) : 26 : 26 : N1LVS04	: 2+0+2 (L+P+SDA) Credits : : 26 CIE Marks : : 26 SEE Marks :

Course Objective: To study and design various digital circuits and systems using Verilog Hardware Description Language (HDL), synthesize and implement on Field Programmable Gate Arrays (FPGAs).

UNIT- I

Introduction to HDL based Digital Design: Design flow and Design styles for digital circuits, Verilog operators, Verilog Primitives, Gate level, Data flow and Behavioural modeling. Delay models, Control statements, Tasks and Functions.

(05+05) Hrs

UNIT- II

Programmable Logic Devices: ROM, PAL, PLA, CPLD, FPGA, FPGA Architecture, FPGA- CLBs, switch Matrix and IOB, Configurable Logic Blocks (CLBs) in Xilinx FPGA –XC3000 and Xilinx Spartan-3, FPGA Design Flow.

FPGA architectures and its usage in embedded Systems: Zynq Ultrascale + MPSoC device architecture. Introduction to Ultrascale Architectecture, System block diagram, High speed serial IO, MIO and EMIO, Functional units and peripherals, Signals interfaces and pins, On chip memory, DMA controller, Reset system, PL peripherals, Vivado design flow, Logic design on Ultrascale + MPSoC FPGA on PL block. Programming and debugging using SDK.

(05+05) Hrs

UNIT- III

Fixed and Floating point Arithmetic: Fixed point number system and floating point number system, Arithmetic operation on Fixed and Floating point numbers.

Combinational circuit design using Verilog:

Ripple Carry adder, Comparators, Combinational Multiplier – Array Multiplier, Unsigned and Signed integer multiplication, Barrel shifter, Tri-State Combinational Circuits.

(05+05) Hrs

UNIT- IV

Sequential Circuit Design using Verilog: Latches, Flip Flops, Shift registers, Counters/ Timers/ Clock Dividers using T Flip Flops, Clock Dividers using D Flip Flops, Synchronous sequential Circuit Design using D and JK Flip Flops.

Finite State Machines (FSM): Finite State Machines and controllers, State diagram, designing FSM using state graph, one-hot-state assignment, controller design. Traffic Light control system.

(05+05) Hrs

UNIT- V

Designing Data path components and Memory units: Serial adder, multiplier using Shift and Add, Fixed point and, Binary Divider, Accumulator, Booth Multiplier, Multiply and Accumulate (MAC) unit, Floating point Multiplier. Memory Design – FIFO, Stack, Circualr Buffer.

(06+06) Hrs

Reference Books:

1	Frank Vahid	Digital Design with RTL Design, VHDL, and Verilo 2 nd , Edition John Wiley and SonsPublishers, 201)g 1.
2	Samir Palnitkar	Verilog HDL A guide to Digital Design an Synthesis 2 nd Edition, Pearson Education, 2017.	ıd
3	Reference Manual	Zynq UltraScale+ Device Technical Reference Manual.	:e

Course Outcomes: The students will be able to

CO1: Select appropriate coding style to write Verilog HDL and implement basic combinational circuits to design digital system component.

CO2: Design combinational circuits using PLDs and discuss the architecture of different FPGAs.

CO3: Design combinational circuits using Verilog HDL and implement on Spartan-3 FPGA.

CO4: Design sequential circuits and State Machine using Verilog HDL and implement on Spartan-3 FPGA.

CO5: Design data path components using Verilog HDL

CO6: Design selected circuit for a particular application using Spartan-3 FPGA. Prepare the report.

Embedded Systems Lab

Lab work Hours/Week	: 1+2+0 (L+P+T)	Credits	:	2.0
Total Lecture Hours Total Lab Hours	: 13 : 26	CIE Marks	:	50
Course Code	: N1LVSL1	SEE Marks	:	50

Course Objectives: Enable students to develop assembly level and C-program for Cortex M3 based microcontrollers to interface input- output devices by configuring on chip peripherals.

List of Experiments –evaluation board:

- 1. Develop a system to implement a calculator which can perform the operations such as addition, subtraction, Logical AND and Logical OR using 4x4 matrix Keypad/Switches and 16x2 LCD/LEDs interfaced to Cortex M3 based microcontroller. (matrix Keypad, LCD/LED)
- 2. Develop a system to implement a Traffic control system using on-chip timer and LEDs/7-segment Displays interfaced to Cortex M3 based microcontroller. (Timer, LEDs/7-segment Display)
- 3. Develop a system to implement a Temperature control system using temperature sensor, on-chip ADC and LCD interfaced to Cortex M3 based microcontrollers. (Signal conditioning circuit, ADC, / LCD, Relay)
- Develop a system to measure/control the rotation speed of DC motor using on-chip timer/PWM module of Cortex M3 based microcontroller. (PWM, DC motor, Switches)
- Develop a system to control the direction of rotation and speed of rotation of Stepper motor interfaced to Cortex M3 based microcontroller. (Stepper motor, Switches/ Push button keys)
- 6. Develop a system to measure the frequency of the input signal/rotation speed of a DC motor interfaced to Cortex M3 based microcontroller. (DC motor, Opto coupler, Timer, LCD)
- Develop a system to control the bottle filling system using Cortex M3 based microcontrollers. (Stepper motor, IR sensors/Proximity, Solenoid valve)
- 8. Develop a system to control the Elevator system using Cortex M3 based microcontrollers. (Stepper Motor, Proximity sensor, 7segement Display, Push button keys).

- 9. Develop a weighing machine using Cortex M3 based microcontrollers. (Signal Conditioning circuit, Load cell, ADC, LCD).
- Develop a Real time clock using Cortex M3 based Microcontroller. (LCD, Timer).

Open ended Experiments:

1. Develop a Washing machine control unit using Cortex M3 based microcontrollers. (LED, Multiplexed 7-segment display, Keypad, Solenoid valve, Motor control (ON/OFF + Speed), Control logic).

Course Outcomes: Students will be able to

- **CO1:** Develop and execute embedded C and Assembly level programs to interface input/output devices to Cortex M3 based microcontroller.
- **CO2:** Develop and execute embedded C and Assembly level program Program to configure On-chip peripherals of Cortex M3 based microcontroller.
- **CO3:** Develop embedded System applications using Cortex M3 based microcontroller.

Department of E&IE, SIT, Tumakuru

ACADEMIC YEAR: 2023-24

Professional Elective-1

ASIC Design

Contact Hours/ Week	: 2 +0+2(L+P+SDA)	Credits: 3.0	
Total Lecture Hours	: 26	CIE Marks: 50	
Total SDA Hours	: 26	SEE Marks: 50	
Course Code	: N1LVSE11		

Course Objective: Design various ASIC configurations, analyze Programmable ASIC memories, and Use CAD tools for ASIC design flow.

UNIT- I

Introduction: Types of ASIC Design, ASIC Design Flow, FPGA design Flow, Programmable logic device, ASIC cell libraries.

(05+05) Hrs

UNIT- II

Data Logic Cells: Data Path Elements, Adders, Multiplier, Arithmetic Operator, I/O cell. **ASIC Library Design**: Logical effort: practicing delay, logical area and logical efficiency logical paths, multi stage cells, optimum delay, optimum no. of stages, library cell design.

(05+05) Hrs

UNIT- III

Low-Level Design Entry: Schematic Entry, **Programmable ASIC**: Anti-fuse, Static RAM, EPROM and EEPROM Technology, FPGA, Programmable ASIC logic cells, ASIC I/O cells, Programmable ASIC Interconnects.

(05+05) Hrs

UNIT- IV

A Brief Introduction to Low Level Design Language: introduction to EDIF, PLA Tools and CFI designs representation. Half gate ASIC. Introduction to Synthesis and Simulation.

ASIC Construction: Physical Design, CAD Tools, System Partitioning, Estimate ASIC size, FPGA Partitioning and its Methods.

(05+05) Hrs

UNIT- V

Floor Planning and Placement and Routing: Physical Design, System Partitioning, Estimating ASIC size, partitioning methods. Floor planning tools, I/O and power planning, clock planning, placement algorithms. Global Routing, Local Routing, Detail Routing, Special Routing, Circuit Extraction and DRC.

(06+06) Hrs

Text Books:

1	M.J.S .Smith	"Application - Specific Integrated Circuits" – Pearson Education, 2003.
2	Jose E.France,	"Design of Analog-Digital VLSI Circuits
	YannisTsividis	for Telecommunication and signal processing",
		2 nd Edition, Prentice Hall, 1993.
3	MalcolmR.Haskard;	"Analog VLSI Design – NMOS and
	Lan. C. May	CMOS", Prentice Hall, 1998.
4	Mohammed Ismail	"Analog VLSI Signal and Information
	and Terri Fiez	Processing", McGraw Hill, 1994.

Course Outcomes: Students will be able to

- **CO1:** Identify and apply appropriate ASIC configuration for particular application.
- **CO2:** Select and apply appropriate techniques to optimize data path and arithmetic components.
- **CO3:** Identify and use Programmable ASIC memories according to design requirements.
- **CO4:** Simulate and synthesize the ASICs.
- **CO5:** Design ASICs using modern CAD tools.
- **CO6:** Design the circuit for a particular application using appropriate tool. Prepare the report.

VLSI Design Automation

Contact Hours/ Week	: 2+0+2 (L+P+SDA)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total SDA Hours	: 26	SEE Marks :	50
Course Code	: N1LVSE12		

Course Objective: To impart knowledge on implementation of automation methods for VLSI physical design.

UNIT- I

Logic Synthesis & Verification: Introduction to combinational logic synthesis, Binary Decision Diagram, Hardware models for High-level synthesis.

VLSI Automation Algorithms: Partitioning: problem formulation, classification of partitioning algorithms, Group migration algorithms, simulated annealing & evolution, other partitioning algorithms.

(05+05) Hrs

UNIT- II

Placement, Floor Planning & Pin Assignment: problem formulation, simulation base placement algorithms, other placement algorithms,

Department of E&IE, SIT, Tumakuru

ACADEMIC YEAR: 2023-24

Text Books:

101

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constraint based floor planning, floor planning algorithms for mixed block & cell design. General & channel pin assignment.

(05+05) Hrs

(05+05) Hrs

UNIT- III

Global Routing: Problem formulation, classification of global routing algorithms, Maze routing algorithm, line probe algorithm, Steiner Tree based algorithms, ILP based approaches.

UNIT- IV

Detailed Routing: problem formulation, classification of routing algorithms, single layer routing algorithms, two layer channel routing algorithms, three layer channel routing algorithms, and switchbox routing algorithms.

Over The Cell Routing & Via Minimization: two layers over the cell routers, constrained & unconstrained via minimization.

(05+05) Hrs

UNIT- V

Scripting Languages: Overview of Scripting Languages – PERL, CGI, VB Script, Java Script. PERL: Operators, Statements Pattern Matching etc. Data Structures, Modules, Objects, Tied Variables. Inter process Communication Threads, Compilation & Line Interfacing.

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(06+06) Hrs

T	NaveedShervani	Kluwer Academic Publisher, 3 rd Edition, 2013
2	ChristophnMeinel & Thorsten Theobold	Algorithm and Data Structures for VLSI Design, KAP, 2002.
3	Rolf Drechsheler	Evolutionary Algorithm for VLSI, Springer, 2 nd Edition, 2013.
4	Randal L, Schwartz Tom Phoenix	Learning PERL, Oreilly Publications, 6th Edition, 2011.

Course Outcomes: Students will be able to,

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- **CO1:** Identify and discuss partitioning algorithms used to design VLSI automation and describe the basic concepts of Logical high level synthesis and verification of hardware models
- **CO2:** Discuss the placement and floor planning algorithms.
- **CO3:** Select suitable routing algorithms in VLSI design automation.
- **CO4:** Discuss routing algorithms with respect to different layers.
- **CO5:** Discuss script languages for VLSI design automation.

VLSI for Digital Signal Processing

Contact Hours/ Week	: 2 +0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N1LVSE13		

Course Objective: Design custom or semi-custom VLSI circuits for Signal Processing applications.

UNIT- I

Introduction: DSP algorithms: FIR and IIR Filters, Representation of DSP Algorithms.

Iteration Bounds: loop bound and Iteration bound, Algorithms for Computing Iteration Bound, Iteration Bound of multi rate data flow graphs.

(05+05) Hrs

UNIT- II

Pipelining and parallel processing: pipelining of FIR Digital Filters, parallel processing, Pipelining and parallel processing for low power.

Retiming: Properties, Solving Systems of Inequalities, Retiming techniques.

(05+05) Hrs

UNIT- III

Unfolding: Algorithm for Unfolding, Properties of Unfolding, Critical path, Unfolding and Retiming, Applications of Unfolding.

(05+05) Hrs

UNIT- IV

Systolic architecture design: systolic array design Methodology, FIR systolic array, Selection of Scheduling Vector, Matrix-Matrix Multiplication and 2D systolic Array Design.

(05+05) Hrs

UNIT- V

Fast convolution–Cook-Toom Algorithm, Winograd Algorithm, Iterated convolution,

Pipelined and Parallel recursive filter: Pipeline Interleaving in Digital Filter, first order IIR digital Filter, Higher order IIR digital Filter, parallel processing for IIR filter, Combined pipelining and parallel processing for IIR Filter, Low power IIR Filter Design Using Pipelining and parallel processing.

(06+06) Hrs

Te	ext Book	
1	KeshabK.Parhi	"VLSI Digital Signal Processing systems, Design and implementation ", Wiley, Inter Science, 1999.
Re	eference Books:	
1	Mohammed Isamail and Terri Fiez	Analog VLSI Signal and Information Processing, Mc Graw-Hill, 1994.
2	S.Y. Kung, H.J. White House, T. Kailath	VLSI and Modern Signal Processing, Prentice Hall, 1985.
3	Jose E. France, YannisTsividis	Design of Analog - Digital VLSI Circuits for Telecommunication and Signal Processing, Prentice Hall, 2 nd Edition, 1994.

Course Outcomes: The students will be able to

- **CO1:** Discuss various DSP algorithms and represent using block diagrams, signal flow graphs and data flow graphs.
- **CO2:** A. Compute the iteration bound using Longest Path Matrix Algorithm and the Minimum Cycle Mean Algorithm.
 - B. Calculate critical path computation time and power consumption in filters
- **CO3:** Perform retiming in filters and select different retiming techniques and algorithm for unfolding.
- **CO4:** Discuss Systolic architecture design methodologies
- **CO5:** Apply various algorithms for efficient implementation of convolution and implement filters using pipelining and parallel processing.

Nano Electronics

Contact Hours/ Week	: 2+0+2(L+P+SDA)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total SDA Hours	: 26	SEE Marks :	50
Course Code	: N1LVSE14		

Course Objective: Enable students to understand various advanced concepts in nanoelectronics and fundamentals on QED, SED, Molecular electronics and spintronics along with computational tools for modelling and simulation of nanoelectronics devices.

UNIT – I

Introduction to Nanoelectronics: Limitations of the conventional MOSFETs at Nanoscales, MOSFET Scaling & implications, Introductory concepts of Ballistic transport and Quantum confinement, Differences in Few Electron Devices (as analog version) and Single Electron Devices (as digital version) of Nanoelectronic devices

Nanostructures and Quantum Electronic Devices: Low-dimensional structures- Quantum wells, Quantum wires and Quantum dots; Density of states in low-dimensional structures; Quantum Interference Devices; Split – Gate Transistor; Electron – Wave Transistor; Resonant tunneling phenomena and its applications in diodes and transistors

(05+05) Hrs

UNIT – II

Molecular Electronic: Overview & Basics; Fabrication of molecular electronics-based transistor devices; Conductivity of organic polymers-Conduction mechanism in organic polymers; Polymer Electronics; Self-Assembling Circuit.

(05+05) Hrs

UNIT – III

Single Electron Devices: Principle of operation- Single-Electron Effect, Coulomb Blockade Phenomenon: Theoretical Quantum Dot Transistor -Energy of Quantum Dot system, Single-Electron Quantum-Dot Transistor, Single transistors; Conductance Oscillation and Potential Fluctuation; Transport under Finite temperature and Finite Bias; Coulomb Blockade Devices. (05+05)Hrs

UNIT – IV

Carbon Nanoelectronics: Carbon nanotubes - SWCNTs and MWCNTs; 1D quantization in nanotubes- van Hove singularities; Fabrication of CNTs; CNT FETs- Device characteristics, CNT-TUBFET, CNT-SET; and NanoWire FETs; Electronic structure of grapheme: FETs- GNRFETs. **(05+05) Hrs**

$\mathbf{UNIT} - \mathbf{V}$

Spintronics: Fundamentals of spintronics: Spintronic devices- spin diodes and spin transistors

Current Nanoelectronic Devices: Quantum Effects in MOSFETs, Strained Silicon, Fully Depleted SOI-MOSFET, Double-Gate MOSFET, Multi-gate MOSFETs, FIN-FET, Electrically Induced Junctions for EJ-MOSFETs, Ballistic Transport, Conductance Quantization, Quantum Point Contact Devices. (06+06) Hrs

Text Books:

1	Shunri	Oda,	David	Nanoscale	Silicon	Device	es, CRC	Press,	Taylor	&
	Ferry			Francis Gr	oup, 20	15.				
2	K. (Goser,	Р.	Nanoelectr	onics a	and N	Vanosyst	æms,	Spring	er,
	Gloseko	otter		2005			-			

Reference Books:

1	Suprio Datta	Lessons from nanoelectronics, World Scientific publisher, 2 nd Edition, 2018			
2	Karl Goser, Peter Glosekotter, Jan Dienstuhl	Nanoelectronics and Nanosystems- From Transistors to Molecular and Quantum Devices, Springer-Verlag 2004.			
3	Supriyo Datta	Quantum Transport-From Atom to Transistor, Cambridge University press, 2012.			

Course Outcomes: Students will be able to

CO1: Discuss the concepts of ballistic transport and quantum confinement.

CO2: Describe the various nanostructures and its applications towards Quantum Electronic Devices.

CO3: Discuss the fundamentals of Molecular Electronics

CO4: Describe the fundamentals of Single Electron Devices and carbon based nanoelectronic devices.

CO5: Discuss the fundamentals of Spintronics.

CO6: Design and simulate various advanced nanoelectronic devices.

II Semester

SIDDAGANGA INSTITUTE OF TECHNOLOGY, TUMAKURU-03

(An autonomous Institute under Visvesvaraya Technological University)

SCHEME OF TEACHING AND EXAMINATION

II SEMESTER M.Tech. VLSI Design and Embedded Systems

	Teaching Hours per Week Exami				Exami	ination					
S1. No.	Course ' Course '	Type and Code	Course Title	Theory	Practical / Seminar	Tutorial / Skill Development Activities	Duration in hrs.	CIE Marks	SEE Marks	Total Marks	Credits
				L	Р	T/SDA					
1.	IPCC	N2LVSI01	Real time operating systems	3	2	0	3	50	50	100	4
2.	PCC	N2LVS02	VLSI Process Technology	3	0	2	3	50	50	100	4
3.	PCC	N2LVS03	Design of IoT Systems	2	0	2	3	50	50	100	3
4.	PEC	N2LVSE2x	Professional Elective – 2	2	0	2	3	50	50	100	3
5.	PEC	N2LVSE3x	Professional Elective – 3	2	0	2	3	50	50	100	3
6.	PEC	N2LVSE4x	Professional Elective 4	2	0	2	3	50	50	100	3
7.	MPS	N2LVSMPS	Mini Project with Seminar	0	4	2		100		100	3
8.	PCCL	N2LVSL1	VLSI DESIGN LAB	1	2	0	3	50	50	100	2
9.	AEC	ARAS	Aptitude Related Analytical Skills	36 I	Hrs. for the semest	he entire ter	2	50	50	100	0
10	AUD/ AEC	N2LVSAUD / N2LVSAEC	BoS Recommended online course	Classes and Evaluation Procedures are as per the policy of the online course providers				0			
			Total	15	8	12		500	400	900	25

Note: **IPCC**-Integrated Professional Core Courses, **PCC**: Professional Core Course, **PEC**: Professional Elective Course, **OEC**- Open Elective Course, **MPS**- Mini Project with Seminar, **PCCL**-Professional Core Course Lab, **AUD/AEC** –Audit Course / Ability Enhancement Course (A pass in AUD/AEC is mandatory for the award of the degree) **L**-Lecture, **P**-Practical, **T/SDA**-Tutorial / Skill Development Activities (Hours are for Interaction between faculty and students)

Professional Elective 2		Profession	al Elective 3	Professional Elective 4		
N2LVSE21	CMOS RF Circuit	N2LVSE31	System on Chip (SoC)	N2LVSE41	DSP Architecture	
	Design		Design			
NOLVEEOO	Mixed Signal Circuit	NOLVEE20	System Varilag	NOI VSE40	Wireless sensor	
112120 01222	Design	NZLV SESZ	System vernog	NZLV SLHZ	network	
NOLVSE02	VLSI Testing and	NOI VOE 22	Low power VLSI	NOI VOE42	Data Structures using	
INZLV SEZS	Verification	NZLV SĽ33	Design.	NZLV SL+5	С	
			Interface and Noise			
NOLVSE04	Design of CMOS Phase	NOI VSF34	control technique	NOI VSF44	RISC V Processor	
INZL V SIZZT	Locked Loops	NZLV SLS4	in Electronic	NZLV SLTT	Design	
			System design			

1. Mini Project with Seminar: This may be hands-on practice, survey report, data collection and analysis, coding, mobile app development, field visit and report preparation, modelling of system, simulation, analysing and authenticating, case studies, etc.

CIE marks shall be awarded by a committee comprising of HoD as Chairman, Guide/co-guide, if any, and a senior faculty of the department. Students can present the seminar based on the completed mini-project. Participation in the seminar by all postgraduate students of the program shall be mandatory.

The CIE marks awarded for Mini-Project work and Seminar, shall be based on the evaluation of Mini Project work and Report, Presentation skill and performance in Question and Answer session in the ratio 50:25:25. Mini-Project with Seminar shall be considered as a head of passing and shall be considered for vertical progression as well as for the award of degree. Those, who do not take-up/complete the Mini Project and Seminar shall be declared as fail in that course and have to complete the same during the subsequent semester. **There is no SEE for this course.**

2. Internship: All the students shall have to undergo a mandatory internship of **06 weeks** during the vacation of II and III semesters. A University examination shall be conducted during III semester and the prescribed internship credit shall be counted in the same semester. The internship shall be considered as a head of passing and shall be considered for vertical progression as well as for the award of degree. Those, who do not take-up/complete the internship shall be declared as fail in the internship course and have to complete the same during the subsequent University examination after satisfying the internship requirements.

Real Time Operating Systems

Contact Hours/Week	: 3+2+0 (L+P+T)	Credits: 4.0
Total Lecture Hours	: 40	CIE Marks : 50
Total Lab Hours	: 26	SEE Marks : 50
Course Code	: N2LVSI01	

Course Objectives: To design and develop embedded applications using realtime operating systems.

UNIT- I

Introduction to Real-Time Embedded Systems: Brief history of Real Time Systems, A brief history of Embedded Systems.

System Resources: Resource Analysis, Real-Time Service Utility, Scheduling Classes, The Cyclic Executive, Scheduler Concepts, Preemptive Fixed Priority Scheduling Policies, Real-Time OS, Thread Safe Reentrant Functions.

Processing:Preemptive Fixed-Priority Policy, Feasibility, Rate Monotonicleastupperbound,NecessaryandSufficientfeasibility.08 Hrs

UNIT- II

Processing: Deadline - Monotonic Policy, Dynamic priority policies.

I/O Resources: Worst-case Execution time, Intermediate I/O, Execution efficiency, I/O Architecture.

Memory: Physical hierarchy, Capacity and allocation, Shared Memory, ECC Memory, Flash file systems. 08 Hrs

UNIT- III

Multi-resource Services: Blocking, Deadlock and livestock, Critical sections to protect shared resources, priority inversion.

Soft Real-Time Services: Missed Deadlines, QOS.

Soft Real-Time Services: Alternatives to rate monotonic policy, mixed hard and soft real-time services.

Embedded System Components: Firmware components, RTOS systemsoftware mechanisms, Software application components.08 Hrs

UNIT- IV

Firmware Components: The 3 firmware components, RTOS system software mechanisms, Software application components.

Debugging Components: Exceptions, assert, Checking return codes. Singlestep debugging, kernel scheduler traces, Test access ports, Trace ports, Power-On self test and diagnostics, External test equipment, Applicationlevel debugging.

Performance Tuning: Basic concepts of drill-down tuning, hardware – supported profiling and tracing, Building performance monitoring into

software, Path length, Efficiency Call frequency, Fundamental optimizations.

08 Hrs

UNIT- V

High availability and Reliability Design: Reliability and Availability, Similarities and differences, Reliability, Reliable software, Available software, Design tradeoffs, Hierarchical applications for Fail-safe design.

Process and Threads: Process and thread creations, Programs related to semaphores, message queue, shared buffer applications involving inter task/thread communication **08 Hrs**

Reference Books:

1 Sam Siewert	"Real-Time Embedded Systems and
	Components" Cengage Learning India Edition,
	2016.
2 Myke Predko	"Programming and Customizing the PIC microcontroller" 3rd Ed, TMH, 2008.
3 Jhon Wiley	"Programming for Embedded Systems"
	Dreamtech Software Team, Jhon Wiley, India
	Pvt. Ltd,2008.

Course Outcomes: The student will be able to

- **CO1:** Discuss the fundamental concepts of real-time operating systems.
- **CO2:** Analyze the system resources required to build RTOS.
- CO3: Analyze the Multi-service resources required for RTOS
- **CO4:** Analyze various performance tuning techniques
- **CO5:** Develop programs for multithreaded applications using suitable techniques.
- **CO6:** Develop C programs to create multithreads and demonstrate the Working and prepare the report.

Practicals for CIE

- 1. Creation of multithreads
- 2. Assigning different priorities to threads
- 3. Threads with same priority
- 4. Priority inheritence
- 5. Communication between Parent and child thread.
- 6. Shared recourse and Semaphore to manage shared recourse
- 7. Communication between a pipe server and a process thread
- 8. PROSIX based message Queue
- 9. Real time Camera interfacing.

VLSI Process Technology

Contact Hours/ Week	: 3+0+2 (L+P+SDA)	Credits :	4.0
Total Lecture Hours	: 40	CIE Marks :	50
Total SDA Hours	: 26	SEE Marks :	50
Course Code	: N2LVS02		

Course objective: Enable students to understand the manufacturing methods and their underlying scientific principles in the context of technologies used in VLSI chip fabrication.

UNIT- I

Introduction: Electronic-Grade Silicon, Czochralski Crystal Growing, Silicon Shaping, Process Considerations. Environment for VLSI technology: clean room and safety requirements, Wafer cleaning process.

Epitaxy: Introduction, Vapour-Phase Epitaxy, Molecular Beam Epitaxy, Epitaxial Evaluation.

Oxidation: kinetics of silicon dioxide growth for thick, thin and ultra-thin films. Oxidation technologies in VLSI and ULSI: Characterization of oxide films; high K and low K dielectrics for VLSI. **O8 Hrs**

UNIT- II

Chemical Vapour deposition techniques: CVD techniques for deposition of polysilicon, silicon dioxide, silicon nitride.

Metallization: Metallization Applications, Metallization Choices, Physical Vapor Deposition (evaporation and sputtering techniques). Failure mechanisms in metal interconnect; multilevel Metallization schemes, New Role of Metallization. **O8 Hrs**

UNIT- III

Impurity incorporation: Models of **Diffusion** in Solids, Fick's laws for Diffusion, Measurement Techniques, Fast Diffusion in Silicon.

Ion implantation: Introduction, Range Theory, Implantation Equipment, Annealing, Shallow Junctions, High-Energy Implantation, annealing; Characterization of impurity profiles.

Reactive Plasma Etching: Introduction, Plasma Properties, Feature-Size Control and Anisotropic Etch Mechanisms, Other Properties of Etch Processes, Reactive Plasma-Etching Techniques and Equipment, Specific Etch Processes. **08 Hrs**

UNIT- IV

Lithography: Introduction, Optical Lithography, Electron Lithography, X-ray Lithography, Ion Lithography.

Thin film Characterization: Overview of thin film characterization, Imaging techniques: Scanning electron microscopy (SEM), AFM, Structural

properties: X-ray diffraction (XRD), **Electrical** properties: Resistance/resistivity – four point probe, Vander Pauw, **Mechanical** properties: Stress-curvature measurements. **08 Hrs**

UNIT- V

VLSI Process Integration: Introduction, Fundamental Considerations for IC Processing, NMOS IC technology, CMOS IC Technology, MOS Memory IC Technology, Bipolar IC Technology, IC Fabrication.

Packaging of VLSI Devices: Introduction, Package Types, Packaging DesignConsiderations.08 Hrs

Text Books:

1	S. M. Sze	VLSI Technology, McGraw-Hill, 2 nd Edition, 2017.
2	S.K. Ghandhi	VLSI Fabrication Principles, John Wiley Inc., New York, 2 nd Edition, 2008.
3	John A. Venables	Introduction to Surface and Thin Films Processes, Cambridge University Press, 2010.

Course Outcomes: students will be able to

- **CO1:** Identify and describe the various processes present in the crystal growth and wafer preparation for Electron grade Silicon. Select appropriate epitaxial growth techniques employed in IC fabrications and discuss each process.
- **CO2:** Select and discuss an appropriate chemical vapor deposition method to deposit polySi, SiO₂ and SiN₃ thin films and metallization process for IC fabrications.
- **CO3:** Identify and select appropriate impurity incorporation method, annealing techniques and reactive plasma etching methods used in IC fabrications
- **CO4:** Identify, select and discuss the various lithography techniques used in IC fabrications. Identify, select and discuss the various characterization techniques (the structural, electrical and mechanical properties) used analyzing the material properties of thin films.
- **CO5:** Identify and describe the various IC fabrication process sequence and special considerations. Select an appropriate package type and discuss design considerations of VLSI devices.
- **CO6:** Deposit the material in thin film using PVD technique and analyze the properties of the deposited film using various characterization techniques in a team. Prepare the report.

List of Activities for CIE.

- 1. Silicon wafer Cleaning (RCA1 and RCA2)
- 2. Glass Substrate cleaning
- 3. Deposition of insulating material (Al2O3/ SiO2) on Si/glass substrate using E beam Evaporation.
- 4. Deposition of metal/ alloys on insulated Si/glass substrate using DC Sputtering.
- 5. Deposition of semiconductor on insulated Si/glass substrate RF Sputtering
- 6. Analyse the structural properties of deposited thin film using XRD and AFM/SEM.
- 7. Determination of sheet resistance of deposited thin film using 4 probe method.

Design of IoT Systems

Contact Hours/ Week	: 2 +0+2 (L+P+SDA)	Credits:	3.0
Total Lecture Hours	: 26	CIE Marks:	50
Total SDA Hours	: 26	SEE Marks:	50
Course Code	: N2LVS03		

Course Objective: To impart the knowledge of components, Communication and development of software required for the design of IoT systems.

UNIT- I

Definition and Characteristics of IoT, IoT architectures and Reference Models, A core IoT functional Stack, Data management and Compute stack. Introduction to the IoT Framework: A brief refresher on the Internet, Communication models and Communication APIs, The IoT Framework, Types of IoT Systems, Challenges of implementing Effective IoT Systems. IoT Levels and Deployment Templates.

(05+05) Hrs

UNIT- II

Basic Python Programming: Python Data types and Data structures, Control flow, Functions, Modules, Packages, File Handling, Data/Time operations, Classes, Python Packages of Interest for IoT.

(05+05) Hrs

UNIT- III

IoT Physical Devices and End points: Introduction to Renesas Synergy kits, Arduino and Raspberry pi boards. Introduction to Sensors, Actuators and Smart objects/sensors, IoT Design methodology. (05+05) Hrs

UNIT- IV

Connecting smart objects: Communications criteria, Wireless sensor networks and its Technologies, Bluetooth, Wi-Fi, Zigbee, LoRa, RFID, IoT Access Technologies. IP as the IoT Network layer, Advantages of internet Protocol(IP), Adoption and Adaption of the IP, Optimizing IP for IoT.

(05+05) Hrs

UNIT- V

IoT protocols: MQTT, XMPP, DDS, AMQP, COAP, REST. Cloud services for IoT(AWS). IoT Web application development: HTML, CSS, JavaScript, MongDB, Python web application framework: Django. Case studies: case study on IoT System for Weather monitoring, Home Automation, Agriculture, Industry.

(06+06) Hrs

Text Books:

1	Arshdeep Bahga, Vijay Madisetti	Internet of Things , A Hands on Approach 1 st Edition, 2015.
2	David Hanes, Gonzalo Salgueiro,Patrick Grossetete, Robert Barton, Jerome Henry	IoT Fundamentals: Networking Technologies, Protocols, and Use Cases for the Internet of Things, Pearson Education (Cisco Press Indian Reprint), (ISBN: 978-9386873743), 1 st Edition, 2018.
3	Sammi salama hussen Hajjaj, Kisheen Rao Gsangaya	The Intenet of Mechanical Things: The IoT Framework for Mechanical Engineers., CRC press Taylor and Francis Group, 1 st Edition 2022,
4	Srinivasa K Srinivasa K.G., Siddesh G.M., Hanumantha Raju R.	Internet of Things, Cengage learning India 1 st Edition, 2018.

Course Outcomes: Students will be able to

CO1: Discuss the building blocks of an IoT system.

- **CO2:** Develop Python programmes and use python packages related to IoT.
- **CO3:** Describe the IoT Design methodology and the operation of end point devices.
- **CO4:** Describe the concept of Wireless sensor networks and different technologies used for IoT.
- **CO5:** Discuss the operation of IoT protocols, develop web applications and prepare case studies for IoT based applications.
- **CO6:** Design the circuit for a particular application using appropriate tool. Prepare the report.

VLSI Design Lab

Lab work Hours/Week	: 1+2+0 (L+P+T)	Credits	:	2.0
Course Code	: N2LVSL1	CIE Marks	:	50
		SEE Marks	:	50

Course Objective: Analyse, Design and simulate digital and analog MOSFET circuits for various applications.

List of Experiments:

- 1. Design a given logical operation using CMOS design style.
- a. Draw the schematic and verify the design parameters with the help of i. Transient Analysis to verify the truth table
- b. Draw the Layout and verify the DRC.
- c. Extract RC and back annotate the same and verify the Design
- 2. Design a CMOS full adder for given specifications.
- a. Draw the schematic and verify the design parameters with the help of
 i. Transient Analysis to verify the truth table
- b. Draw the Layout and verify the DRC.
- c. Extract RC and back annotate the same and verify the Design
- 3. Design a Common Source amplifier with resistive load for given specifications.
- a. Draw the schematic and verify the design parameters with the help of i. DC Analysis (Calculate the theoretical value for Av)

ii. Transient Analysis (Verify theoretical value of Av with its Practical value).

- b. Draw the Layout and verify the DRC, LVS
- c. Extract RC and back annotate the same and verify the Design
- 4. Design a Common Source amplifier with Active load using Current mirror for given specifications.

Complete the design flow mentioned below:

- a. Draw the schematic and verify the design parameters with the help of
 - i. DC Analysis (Calculate the theoretical value for Av)
 - ii. Transient Analysis (Verify theoretical value of Av with its Practical value).
- b. Draw the Layout and verify the DRC, LVS
- c. Extract RC and back annotate the same and verify the Design
- 5. Design a Common drain amplifier with Active load for given specifications. Complete the design flow mentioned below:
- a. Draw the schematic and verify the design parameters with the help of

- i. DC Analysis (Calculate the theoretical value for Av)
- ii. Transient Analysis (Verify theoretical value of Av with its Practical value).
- b. Draw the Layout and verify the DRC, LVS
- c. Extract RC and back annotate the same and verify the Design
- 6. Design a Differential Amplifier with Active load using Current mirror for given specifications.
- Complete the design flow mentioned below:
- a. Draw the schematic and verify the design parameters with the help ofi. DC Analysis (Calculate the theoretical value for Av)
 - ii. Transient Analysis (Verify theoretical value of Av with its Practical value).
- b. Draw the Layout and verify the DRC, LVS.
- c. Extract RC and back annotate the same and verify the Design.
- 7. Design a Operational Amplifier with Active load using Current mirror for given specifications.
- Complete the design flow mentioned below:
- a. Draw the schematic and verify the design parameters with the help of
 i. DC Analysis
 - ii. Transient Analysis
- b. Draw the Layout and verify the DRC, LVS
- c. Extract RC and back annotate the same and verify the design
- 8. Design a 4 bit binary weighted DAC / 4-bit R-2R Ladder DAC for given specifications.

Complete the design flow mentioned below:

- a. Draw the schematic and verify the design parameters with the help of
 i. DC Analysis
 - ii. Transient Analysis
- b. Draw the Layout and verify the DRC, LVS
- c. Extract RC and back annotate the same and verify the design

Course Outcomes: Student will be able to

- **CO1:** Analyze and Design analog circuits and simulate using EDA tool and prepare the report.
- **CO2:** Analyze and Design digital circuits and simulate using EDA tool and prepare the report.

Professional Elective- 2

CMOS RF Circuit Design

Contact Hours/ Week	: 2+0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE21		

Course Objective: To impart the knowledge on designing CMOS RF Circuit. **UNIT- I**

Introduction to RF Design and Wireless Technology: Design and Applications, Complexity and Choice of Technology. Basic concepts in RF design: Nonlinearly and Time Variance, Intersymbol interference, random processes and noise, Sensitivity and dynamic range, conversion of gains and distortion, characteristics of passive IC components, resistor, capacitor and inductor. **(05+05) Hrs**

UNIT- II

RF Modulation: Analog Modulation: Amplitude Modulation, Phase and Frequency Modulation, Digital modulation: Basic concepts, Binary Modulation, Quadrature Modulation. Power efficiency of modulation schemes, Coherent and Non-coherent detectors. Mobile RF communication, basics of multiple access techniques and wireless standards. **(05+05) Hrs**

UNIT- III

Transceiver Architectures: Receiver Architecture: Heterodyne, Homo dyne, Image Reject Receiver and Transmitter Architecture.

Distributed Systems: Transmission lines, reflection coefficient, the wave equation, examples, Lossy transmission lines, Smith charts – plotting gamma.

High Frequency Amplifier Design: Bandwidth estimation using opencircuit time constants, Bandwidth estimation using short-circuit time constants, Rise time, delay and bandwidth, Zeros to enhance band width, Shunt-series amplifiers, tuned amplifiers, and Cascaded amplifiers.

(05+05) Hrs

UNIT- IV

Low noise Amplifier design: CS stage: Inductive load, Resistive Feedback, Inductive degeneration. Variants of CS LNA, Noise – Cancelling LNAs, Differential LNAs. Non linearity Calculations in LNAs.

Mixers: Mixer Nose Figures, Port – Port Feed through, Single –balanced and double balanced Mixers, Introduction to Passive and Active Mixers.

(05+05) Hrs

UNIT- V

Oscillators: General Principles: Feedback view, One-Port view, Cross-Coupled Oscillator, Three – Point Oscillators. Voltage Controller Oscillators (VCO): Tuning Limitations, Effect of varactor Q, VCOs with wide tuning Range. Effect of Phase Noise, Low noise VCOs.

Phase Locked Loop (PLL): Type – I PLLs: VCO phase Alignment, Dynamics of Type – 1 PLLs, Frequency Multiplication, drawbacks of Type – 1 PLL. Type-II PLLs: Phase/Frequency Detectors, Charge Pumps, Charge-Pump PLLs, Transient Response.

Integer N Frequency Synthesizer: Basic integer N Frequency Synthesizer,Setting behavior, Spur reduction technique.(06+06) Hrs

Text Books:

1	B. Razavi	RF Microelectronics, PHI, 2 nd Edition, 2011		
2	R. Jacob Baker, H.W. Li,	CMOS Circuit Design, layout and		
	D.E. Boyce	Simulation, PHI, 2 nd Edition, 2004.		
3	Thomas H. Lee	Design of CMOS RF Integrated Circuits,		
		Cambridge University press, 2 nd Edition,		
		2003.		
4	Y.P. Tsividis	Mixed Analog and Digital Devices and		
		Technology, TMH, 2010		

Course Outcomes: Students will be able to,

- **CO1:** Discuss the performance parameters to be considered for the design of RF circuits.
- **CO2:** Identify, select and describe the modulations technique and RF communication concepts for RF circuit design.
- **CO3:** Discuss various Transceiver architecture and bandwidth estimation techniques.
- **CO4:** Identify and discuss the general considerations of low noise amplifiers and concepts of mixers.
- **CO5:** Discuss the modeling of various devices at RF Frequency and general principles of oscillators and PLL. Design RF modulation modules and various amplifiers using Matlab Simulink. Prepare the report.

Department of E&IE, SIT, Tumakuru

ACADEMIC YEAR: 2022-23

Mixed Signal Circuit Design

Contact Hours/ Week	: 2+2+0 (L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE22		

Course objective: Enable students to understand the various integrated based filters, data converters, integrated circuit of oscillators and PLLs in IC design.

UNIT- I

Submicron CMOS Circuit Design

Submicron CMOS: Overview and Models, CMOS process flow, Capacitors and Resistors. Digital circuit design: The MOSFET Switch, Delay Elements, An Adder. Analog Circuit Design: Biasing, Op-Amp Design, Circuit Noise.

UNIT-II

(05+05) Hrs

UNIT-III

Data Converter Architectures

using Noise shaping.

Integrator Based CMOS Filters

DAC Architectures- Resistor string, R-2R ladder Networks, Current Steering, Charge Scaling DACs, Cyclic DAC, and Pipeline DAC. ADC Architectures-Flash, Two-step flash ADC, Pipeline ADC, Integrating ADC's, Successive Approximation ADC.

UNIT- IV

Data Converter Modeling and SNR

Sampling and Aliasing: modeling approach, Impulse sampling, The sample and Hold, Quantization noise. Data converter SNR: An overview, Clock Jitter, Improving SNR using Averaging, Decimating filter for ADCs, Interpolating filter for DACs, Band pass and High pass sinc filters - Using feedback to improve SNR.

(05+05) Hrs

UNIT- V

Oscillators and PLL

LC oscillators, Voltage Controlled Oscillators. Simple PLL, Charge pumps PLLs, Non ideal effects in PLLs, Delay Locked Loops. (06+06) Hrs

Integrator Building Blocks- low pass filter, Active RC integrators, MOSFET-C Integrators, gm- C integrators, discrete time integrators. Filtering Topologies:

The Bilinear transfer function, The Biquadratic transfer function, Filters

(05+05) Hrs

(05+05) Hrs

Course Outcomes: students will be able to

CO1: Describe the concepts for mixed signal MOS circuit.

CO2: Analyze the characteristics of IC based CMOS filters.

CO3: Design various data converter architecture circuits.

CO4: Analyze the signal to noise ratio and modeling of mixed signals.

CO5: Design oscillators and phase lock loop circuit.

Text Books:

1	R.Jacob Baker	CMOS Mixed Signal Circuit Design, Wiley		
		India, IEEE Press, reprint 2008.		
2	R.Jacob Baker	CMOS Circuit Design, Layout and		
		Simulation, Wiley India, IEEE Press, 2nd		
		Edition, reprint, 4th Edition, 2019.		
3	Behzad Razavi	Design of Analog CMOS Integrated Circuits,		
		McGraw Hill, 2 nd Edition, 2017.		

VLSI Testing and Verification

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Contact Hours/ Week	: 2+0+2 (L+P+SDA)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total SDA Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE23		

Course Objective: Enable students to understand fault model and

generate test vectors for digital circuits and discuss various verification tools.

UNIT- I

Introduction to Testing: Testing Philosophy, Role of Testing, Digital and Analog VLSI Testing, VLSI Technology Trends Affecting Testing. **Faults:** Single Stuck at faults, Temporary Faults. Bridging faults, Transient faults.

Fault modeling: Fault equivalence, dominance and collapsing.

Fault Simulation: parallel, concurrent and deductive simulation.

(05+05) Hrs

UNIT- II

Test Generation for Combinational Logic Circuits: Test Generation Techniques for Combinational Circuits: Truth table method, Fault matrix method, Boolean difference method, Path sensitization method, D-Roth algorithm, PODEM and FAN. Detection of Multiple Faults in Combinational Logic Circuits.

(05+05) Hrs

UNIT- III

Design of Testable Sequential Circuits: Controllability and Observability, Ad Hoc Design Rules for Improving Testability, The Scan-Path Technique for

Testable Sequential Circuit Design, Level-Sensitive Scan Design, Random Access Scan Technique, Partial Scan, Testable Sequential Circuit Design Using Nonscan Techniques, Crosscheck, Boundary Scan.

(05+05) Hrs

UNIT- IV

Built-In Self Test: Test Pattern Generation for BIST, Output Response Analysis, BIST Architectures-BILBO.

Testable Memory Design: RAM Fault Models, Test Algorithms for RAMs: March algorithm(Row, Column), galloping algorithm, butterfly algorithm, Neighbourhood Pattern Sensitive Faults(NPSF), Detection of Pattern Sensitive Faults, BIST Techniques for Ram Chips, Test Generation and BIST for Embedded RAMs.

(05+05) Hrs

UNIT- V

Importance of Design Verification: The importance of verification, Reconvergence model, Formal verification, Assertion based verification, Equivalence checking, model checking, and functional verification.

Verification Tools: Linting tools: Limitations of linting tools, lintingverilog source code, linting VHDL source code, lintingOpenVera and e-source code, code reviews.

Simulators: Stimulus and response, Event based simulation, cycle based simulation, Co-simulators, verification intellectual property: hardware modelers, waveform viewers.

Verification plan: The role of verification plan: specifying the verification plan, Levels of verification: unit level verification, reusable components verification, ASIC and FPGA verification, system level verification, board level verification. (06+06)Hrs

Text Books:

1	P. K. Lala	Digital	Circuit	Testing	and	Testability,
		Acader	nic Press	s, 1997.		
2	M.L. Bushnell and V.D.	Essential	ls of Ele	ectronic 7	ſesting	for Digital,
	Agrawal	Memory	and M	ixed-Sign	al VL	SI Circuits,
		Springer,	, 1st Co	rrected E	dition	2002, Corr.
		2nd print	ting 2004	4.		

Course Outcomes: Students will be able to

- **CO1:** Identify and generate test for the faults in digital circuits. Identify and apply the appropriate test generation technique for combinational circuits.
- **CO2:** Identify and apply the appropriate Ad Hoc techniques to improve testability of sequential circuits.
- **CO3:** Select appropriate algorithms to test memory elements.
- **CO4:** Discuss verification plan and verification tools.
- **CO5:** Analyze the circuits for static timing verification. Design software algorithm or hardware circuit to test the IC. Prepare report on the same.
- **CO6:** Design the circuit for a particular application using appropriate tool. Prepare the report.

Design of CMOS Phase Locked Loops

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Contact Hours/ Week	: 2+0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE24		

Course Objective: To impart the knowledge of designing phase locked loops, Delay locked loops.

UNIT-I

Introduction: Introduction to Phase locked loops (PLLs), Basic operation of PLL and DLL architectures. Steady state analysis of basic PLL architectures.

(05+05) Hrs

UNIT-II

Designing PFD and Charge pump: Phase detectors, Phase frequency detectors, Charge pump, Loop filters, Introduction to Charge pump based PLLs, Design methodology of charge pump based PLLs.

(05+05) Hrs

UNIT-III

Oscillators: Basic principles, Cross coupled oscillators, Voltage controlled oscillators, VCOs with wide tuning range, Basic concepts, of phase noise. Inverter based Ring oscillators, Basic differential ring oscillators.

(05+05) Hrs

UNIT-IV

Frequency synthesis: Introduction to frequency synthesis, Basic Integer N – Synthesizer, Divider design: Pulse swallow divider, Dual modulus divider,

Divider logic styles. Fractional N – Synthesizer: Basic concepts, Fractional divider using Delta sigma modulation technique. **(05+05) Hrs**

UNIT-V

Digital PLL (DPLL): Basic architecture of DPLL, Basic operation of Time to Digital conversion (TDC), Vernier TDC, Digitally controlled oscillator. Basics of Digital filters.

Clock and Data recovery circuits: Basic idea of clock and data recovery circuits, Bang-Bang Phase detector, Alexander phase detector, Hogge Phase detector.

(06+06) Hrs

Text Books:

1	Behzad Razavi	Design of CMOS Phase locked loops, from level to Architecture level, Cambridge uni press, 2020.	circuit iversity
2	Behzad Razavi	RF microelectronics, 2 nd Edition P education 2012	Pearson

Reference Books:

1	F. Gardner	Phaselock Techniques, John Wiley & Sons,	
		2005.	
2	R. Best	Phase-Locked Loops : Design, Simulation,	
		and Applications, McGraw Hill, 2007.	

Course Outcomes: students will be able to

CO1: Analyze PLL architecture.

CO2: Analyze and design PFDs and Charge pumps

CO3: Analyze and design VCOs and Ring oscillators.

CO4: Analyze and design dual modulus, integer -N and fractional dividers, Charge pump based Integer N and fractional PLLs.

CO5: Discuss the basics of Digital PLLs and Clock and data recovery circuits.

Professional Elective-3

System on Chip Design

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Contact Hours/ Week	:2+0+2(L+P+SDA)	Credits : 3.0
Total Lecture Hours	: 26	CIE Marks : 50
Total SDA Hours	: 26	SEE Marks : 50
Sub. Code	: N2LVSE31	

Course Objective (CO): Enable students to learn the System on Chip design with different approaches and understand the concepts of embedded memories and network on chip topologies.

UNIT- I

Motivation for SoC Design - Review of Moore's law, benefits of system-onchip integration in terms of cost, power, and performance. Typical goals in SoC design – cost reduction, power reduction, design effort reduction, performance maximization. Productivity gap issues and the ways to improve the gap. Comparison on System-on-Board, System-on-Chip, and System-in-Package

System On Chip Design Process: Canonical SoC Design, System Design flow - waterfall design flow, Spiral design flow, Top-down vs Bottom up design flows and Construct by Correction.

(05+05) Hrs

UNIT- II

System level design issues

Specification requirement, Types of Specification. Standard Model: - Soft IP vs Hard IP. Role of Full-Custom Design in Reuse. Design for Timing Closure: Logic Design Issues and Physical Design Issues. Design for Verification: Verification Strategy. System Interconnect and On-Chip Buses. Design for Bring-Up and Debug. Design for Low Power. Design for Test: Manufacturing Test Strategies. Prerequisites for Reuse

(05+05) Hrs

UNIT- III

Macro Design Process: Overview of IP Design, Key Features, Planning and Specifications, Macro design and Verification. Developing Hard Macros: Overview, Design Issues for Hard Macros, Hard Macro Design Process, Productization of Hard Macros.

(05+05) Hrs

UNIT- IV

SoC Verification: -Verification technology options, Verification methodology, Verification languages, Verification IP Reuse, approaches. Verification and Device Test, Verification Plans. UVM overview, VLSI Packaging: Introduction, Packaging, Power Distribution, Input/Output, Chip-Package Co-design.

(05+05) Hrs

UNIT- V

Embedded Memories –cache memories, flash memories, embedded DRAM. Topics related to cache memories. Cache coherence. MESI protocol and Directory-based coherence.

Interconnect architectures for SoC: Bus architecture and its limitations. Network on Chip (NoC) topologies. Mesh-based NoC. Routing in an NoC. Packet switching and wormhole routing.

MPSoCs: Introduction to MPSoCs, Techniques for designing MPSoCs.

(06+06) Hrs

Text Books:

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		Sudeep Pasricha and	On-Chip Communication Architectures:
	1		System on Chip Interconnect, Morgan
		NIKIIDUU	Kaufmann Publishers, 2008
		Rao R. Tummala,	Introduction to system on package sop-
	2	MadhavanSwaminathan	Miniaturization of the Entire System,
			McGraw-Hill, 1 st Edition, 2008.
		Michael Kesting Diama	Reuse Methodology Manual for System on
	3	Driver d	Chip designs, Kluwer Academic Publishers,
		Bricaud	2 nd edition, 2008
1			

Course Outcomes: Students will be able to

- **CO1:** Describe the benefits and different design process of SoC.
- CO2: Discuss System-Level Design Issues, Rules and Tools.
- CO3: Identify and select an appropriate macro design style for SOC design
- **CO4:** Analyze the various methods of SOC verification issues and packaging techniques.
- **CO5:** Analyze cache protocols, NOC topology and describe the design concepts of different types of MPSoCs.
- **CO6:** Design selected circuit for a particular application using appropriate tool. Prepare the report.

System Verilog

Contact Hours/ Week	: 2+0+2(L+P+SDA)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total SDA Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE32		

Course Objectives: To impart the knowledge on system Verilog language to design, assertion and verify functionality of the system.

UNIT- I

Basics of Verification: Difference between ASIC verification and ASIC testing, Verification basics, Test benches, Layered Organization of Test benches. Importance of hardware verification languages and methodologies. **System Verilog data types and typedefs:** System Verilog data types, enhanced literal numbers syntax, 4-state and 2-state types, typedefs, enum, struct data type, Type parameters, \$unit and \$root. Packages, strings, static and dynamic type casting, Random number generation.

(05+05) Hrs

UNIT- II

System Verilog operators, loops, jumps, functions: loops and jumps in system verilog, introduction to different always blocks, system verilog enhancements to tasks and functions, system verilog priority and unique modifiers for case and if statements, 'time scale, system verilog time unit and time precision.

Structs, Unions, Packed and Unpacked Arrays, Semaphores and Mailboxes: Structs and its assignments, packed and unpacked arrays, array indexing, structs and packed structs, Unions and packed unions, dynamic arrays and methods, for each loop, associative arrays and methods, queues and concatenation operations, queue methods, semaphores and methods, Mail boxes and methods, bounded and unbounded mail boxes.

(05+05) Hrs

UNIT- III

Class and Randomization: System verilog class basics, class declaration, class members and methods, class handles, class object construction, super and this keywords, object handles, user defined constructors, class extension and inheritance, chaining new() constructors, overriding class methods, extending class methods, local and protected keywords, constrained random variables, directed vs random testing, rand and randc

class data types, randomize-randomizing class variables, random case, built-in-randomization methods, random sequence and examples.

(05+05) Hrs

UNIT- IV

Interfaces: Interface overview, generic interfaces, interfaces vs records, how interfaces work, requirements of good interface, interface constructs, interface mode ports.

Program block: Fundamental test bench construction, program blocks, program block interaction with modules, final blocks, Test-bench stimulus/Verification vector timing strategies.

Clocking: Clocking blocks, clocking skews, clocking block scheduling, forkjoin processes.

(05+05) Hrs

UNIT- V

Constrained Random variables, Coverage, Methods and interfaces: Randomization constraints, simple and multi-statement constraints, constraint distribution and set membership, constraint distribution operators, external constraints, covergroups, coverpoints, coverpoint bins and labels, cross coverage, covergroup options, coverage capabilities. Virtual class, why to use virtual class, virtual class methods and restrictions, polymorphism using virtual methods, pure virtual methods, pureconstraints, passing type parameters, virtual interfaces.

(06+06) Hrs

Text Books:

1	Christian B Spear	"SystemVerilog for Verification: A guide to learning the Testbench language features", Springer publications, 3 rd edition, 2010.
2	VijayaRaghavan	"SystemVerilog Assertions", Springer publications, 2005
3	Sutherland	"Systemverilog for Design", Springer publications, 2006

Course Outcomes: Students will be able to

- **CO1:** Identify and use appropriate data types for system Verilog programming.
- **CO2:** Select and apply appropriate program constructs for System design.
- **CO3:** Select and apply appropriate methods to write test benches.
- **CO4:** Identify, select and apply different clocking schemes for optimization of designs.

- **CO5:** Discuss constrained Random variables, Coverage, Methods and interfaces
- **CO6:** Design selected circuit for a particular application using appropriate tool. Prepare the report.

Low Power VLSI Design

Contact Hours/ Week	: 2+0+2(L+P+T)	Credits:	3.0
Total Lecture Hours	: 26	CIE Marks:	50
Total Tutorial Hours	: 26	SEE Marks:	50
Course Code	: N2LVSE33		

Course Objective: Analyze and estimate power at different abstraction levels of CMOS VLSI circuits.

UNIT- I

Introduction: Need for low power VLSI chips, Sources of power dissipation on Digital Integrated circuits. Emerging Low power approaches, Physics of power dissipation in CMOS devices. **Device & Technology Impact on Low Power:** Dynamic dissipation in CMOS, Transistor sizing & gate oxide thickness, Impact of technology Scaling, Technology & Device innovation.

(05+05) Hrs

UNIT- II

Power estimation, Simulation Power analysis: SPICE circuit simulators, gate level logic simulation, capacitive power estimation, static state power, gate level capacitance estimation, architecture level analysis, data correlation analysis in DSP systems, Monte Carlo simulation.

(05+05) Hrs

UNIT- III

Probabilistic power analysis: Random logic signals, probability & frequency, probabilistic power analysis techniques, signal entropy.

Low Power Design Circuit level: Power consumption in circuits. Flip Flops & Latches design, high capacitance nodes, low power digital cells library.

(05+05) Hrs

UNIT- IV

Logic level: Gate reorganization, signal gating, logic encoding, state machine encoding, pre-computation logic. **Low power Architecture & Systems:** Power & performance management, switching activity reduction, parallel architecture with voltage reduction, flow graph transformation, low power arithmetic components, low power memory design.

(05+05) Hrs

UNIT- V

Low power Clock Distribution, **Algorithm & Architectural Level Methodologies:** Introduction, design flow, Algorithmic level analysis & optimization, Architectural level estimation & synthesis.

(06+06) Hrs

Text Books:

1	Kaushik	Roy,	Sharat	"Low-F	Power	CMOS	VLSI	Circuit	Design"
	Prasad			Wile	y, 200	9			
2	Gary K. Y	eap		"Practi	ical Lo	w Powe	r Digit	al VLSI	Design",
				KAP, 2	2008.				
3	Rabaey, F	Pedram		"Low	Power	Design	Metho	dologies"	Kluwer
				Acade	mic, 20	009.			

Course Outcomes: Students will be able to

- **CO1:** Analyze the impact of low power in VLSI circuits.
- CO2: Recognize Role of simulation possible at various levels of design.
- **CO3:** Describe the relationship of probability while calculating power dissipation of circuits.
- **CO4:** Apply power reduction techniques at circuit and architectural level.
- **CO5:** Discuss different clock distribution techniques in low power VLSI design.

Interference and noise control techniques in ESD

Contact Hours/ Week	: 2+0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE34		

Course Objectives: Enables student to understand the fundamentals of interference and noise control techniques in electronic design.

UNIT- I

Basic Concept of Instrumentation Design: Needs Analysis with respect to systems deployed in Medical, Industrial, Test and Measurement, Home Appliances, Military Functional requirements & Specifications, Impact on the design due to adverse Electrical, Thermal and Mechanical Operational Environments.

Noise Sources: Electrical, Magnetic, RF, Static, Ground Loops, Shielding, near and far field, shielding effectiveness, absorption and reflection loss, shielding with magnetic material, contact protection, glow and arc discharges, loads with high inrush current, Inductive and resistive load contact protection networks for inductive loads, intrinsic noise sources

Transient EMI, Time domain Vs Frequency domain EMI, Units of measurement parameters, Emission and immunity concepts, ESD.

(05+05) Hrs

UNIT- II

EMI / EMC STANDARDS: ESD, inductive charging human body model, ESD protection in equipment design, Preventing ESD entry, Transient Hardened software Design, Hardening Sensitive Circuits, input filters, clamping suppressors

Civilian standards: FCC, CISPR, IEC, EN, Military standards - MIL STD 461D/462, EMI Test Instrument /Systems, EMI Shielded Chamber, Open Area Test Site, TEM Cell, Sensors/Injectors/Couplers, Test beds for ESD and EFT. **(05+05) Hrs**

UNIT- III

Electronic design guidelines: Noise in electronic circuits. Capacitive and inductive coupling and effect of shield, shielding to prevent magnetic radiation, co-axial and twisted pair cable, grounding, safety ground, signal ground, single and multi-point ground, Hybrid ground, grounding of cables shields, Ground loops and low frequency and high frequency analysis of common mode signals, guard shields Bonding, Isolation Transformer, Transient Suppressors, Cable Routing, Signal Control, Component Selection and Mounting. **(05+05) Hrs**

UNIT- IV

PCB Design Guidelines. NEMA, DIN, BSI, ANSI standards Index protection (IP), cable design guidelines; Printed circuit board design guideline, layout scheme, grid systems, PCB size, Design rules for digital circuits, and Design rules for analog circuits, single and multilayer PCB, CE / Underwrites Laboratories (UL) Compliance.

PCB Traces Cross Talk, Impedance Control, Power Distribution Decoupling, Zoning, Motherboard Designs and Propagation Delay Performance Models.

(05+05) Hrs

UNIT- V

Failure Mechanism and Faulty Tolerance Reliability of electronic components, component types and failure mechanisms, Electronic system reliability prediction, Reliability in electronic system design; software errors, software structure and modularity, fault tolerance, software reliability, prediction and measurement, hardware/software interfaces.

Test for Reliability: Test environments, testing for reliability and durability, failure reporting, Pareto analysis, Accelerated test data analysis, CUSUM charts, Exploratory data analysis and proportional hazards modeling, reliability demonstration, reliability growth monitoring. **(06+06) Hrs**

Text Book:

1	Henry OTT	Noise	reduction	Techniques	in	Electronics
		Circuit	, Wiley Inter	national, Sec	ond	ed., 2009.

Reference Books:

1	W. Prasad Kodali	Engineering Electromagnetic Compatibility: Principles, Measurements and Technologies and Computer Models, Wiley, IEEE Press, 2 nd Edition, 2001
0	Honmy W. Ott	2001. Fleetromagnetic Compatibility Engineering John
4	Henry W. Ott	Wiley and Sons, 1 st Edition, 2009.
3	Bernhard Keiser	Principles of Electromagnetic Compatibility, Artech house, 3 rd Edition, 1998.
4	Balguruswamy	Reliability Engineering, TATA McGraw-hill Publication, 3 rd Edition, 2017
5	Walter C. Bosshart	Printed Circuit Board, Tata McGraw-Hill publication, 3 rd Edition, 2009.

Course Outcomes: The students will be able to

- **CO1:** Analyze the requirement of Instrument and systems. Identify the sources of Noise
- **CO2:** Discuss the various EMI / EMC standards.
- **CO3:** Design various electronic circuits, noises identification and appropriate elimination methods related to instrument and system.
- **CO4:** Discuss the various Guidelines for PCB Design.
- **CO5:** Estimate, analyze, improve the reliability of instrument and system.

Professional Elective- 4

DSP Architecture

Contact Hours/ Week	: 2+0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE41		

Course Objective: Enables student to understand DSP algorithms, architecture and interfacing of peripheral devices to the DSP processor.

UNIT- I

Introduction to Digital Signal Processing:

Introduction : Review of Digital Signal – Processing System, The Sampling Process, Discrete Time Sequences, Discrete Fourier Transform (DFT) and Fast Fourier Transform (FFT), Linear Time-Invariant Systems, Digital Filters, Decimation and Interpolation. Fixed point and Floating point processors.

Computational Accuracy in DSP Implementations: Number Formats for Signals and Coefficients in DSP Systems, Dynamic Range and Precision, Sources of Error in DSP Implementation.

(05+05) Hrs

UNIT- II

Architectures for Programmable Digital Signal – Processing Devices:

Introduction, Basic Architectural Features, DSP Computational Building Blocks, Bus Architecture and Memory, Data Addressing Capabilities, Address Generation Unit, Programmability and Program Execution, Speed Issues, Features for External Interfacing.

(05+05) Hrs

UNIT- III

Programmable Digital Signal Processors:

Introduction, Commercial Digital Signal-processing Devices, Data Addressing Modes of TMS32OC54XX, Memory Space of TMS32OC54xx Processors, Program Control. Detail Study of TMS320C54X & 54xx Instructions and Programming,

On – Chip Peripherals and Interrupts of TMS32OC54XX Processors, Pipeline Operation in TMS32OC54xx Processor.

(05+05) Hrs

UNIT- IV

Implementation of Basic DSP Algorithms:

Introduction, The Q – notation, FIR Filters, IIR Filters, Interpolation and Decimation, Filters, PID controller.

Implementation of FFT Algorithms:

Introduction, An FFT Algorithm for DFT Computation, Overflow and Scaling, Bit – Reversed Index Generation & Implementation on the TMS32OC54xx.

(05+05) Hrs

(06+06) Hrs

UNIT- V

Interfacing Memory and Parallel I/O Peripherals to Programmable DSP Devices:

Introduction, Memory Space Organization, External Bus Interfacing Signals. Memory Interface, Parallel I/O Interface, Programmed I/O, Interrupts and I/O Direct Memory Access (DMA).

Interfacing and Applications of DSP Processors:

Introduction, Synchronous Serial Interface, A CODEC Interface Circuit, DSP Based Bio-telemetry Receiver, Speech Processing System, Image Processing System.

Te	ext Book			
1	Avatar Singh and S. Srinivasan	Digital Signal Processing, Thomson Learning, 2004.		
Reference Books:				
1	Ifeachor E. C., Jervis B.	Digital Signal Processing: A practical approach, W Pearson-Education, PHI, 2002.		
2	B Venkataramani and M Bhaskar	i Digital Signal Processors, TMH, 2nd, 2017.		
3	Peter Pirsch	Architectures for Digital Signal Processing, John Weily, 2009.		

Course Outcomes: The students will be able to

- **CO1:** Apply the knowledge of DSP computational building blocks to develop DSP architecture or processor based applications.
- **CO2:** Apply the knowledge of various types of addressing modes, interrupts, peripherals and pipelining structure of TMS320C54xx processor.

CO3: Develop C-program to configure on-chip peripherals of TMS320C54xx processor.

CO4: Develop DSP algorithms and implement on TMS320C54xx processor.

CO5: Interface Memory and I/O devices to TMS320C54xx processor.

Wireless Sensor Network

Contact Hours/ Week	: 2+0+2(L+P+SDA)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total SDA Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE42		

Course Objectives: Enable students to understand WSN technology that emphasis on standardization of basic sensor systems, medium access protocols and network layer issues.

UNIT- I

Introduction and overview of Wireless Sensor Network(WSN), commercial and scientific applications of WSN, Category of Applications of WSN, Challenges for WSN, Enabling Technologies for WSN.

(05+05) Hrs

UNIT- II

Single node Architecture: Hardware Components, Energy consumptions of Sensor nodes, Operating Systems and Execution Environments, Examples of Sensor nodes, Network Architecture : WSN Scenarios, Optimization Goals and figure of Merits, Design principles for WSNs, Service Interface for WSNs, Gateway Concepts.

(05+05) Hrs

UNIT- III

Physical Layer: Wireless Channel and Communication Fundamentals, Physical Layer & Transceiver Design Considerations in WSN, MAC Protocols: Fundamentals, MAC Protocol for WSNs, IEEE802.15.4 MAC Protocol, and Routing Protocols: Gossip and agent based unicast protocols, Energy Efficient Unicast, Broadcast and Multicast, Geographic Routing, Transport Control Protocols: Traditional Protocol, Design issues.

(05+05) Hrs

UNIT- IV

Sensor tasking and Control: Introduction to Sensor Tasking, Joint Routing Information Aggregation, Sensor Network databases: Challenges Query Interfaces, In-Network Aggregation, Data Centre Storage.

(05+05) Hrs

UNIT- V

Operating System for Sensor Networks: Introduction, Design Issues, Examples of Operating Systems, Node Level Simulators, Performance and Traffic Management Issues: WSN Design Issues, Performance modelling of WSNs, Emerging Applications. (06+06) Hrs

Text Books:

1.	Kazem	"Wireless Sensor Networks: Technology,
	Sohraby,Daniel	Protocol and Applications" John wiley &
	Minoli,Taieb	sons.
	Znati	
2.	Holger Karl, Andreas Wiling	"Protocols and architectures for wireless sensor networks" John wiley & sons, 2011

Reference Books:

1.	Feng Zaho, Leonidas Guibas	"Wireless sensor Networks; An Information Processing Approach" ,Elsevier 2004
2.	C.S. Raghavendra, Krishna, M,Shivalingam, Taieb Znati	"Wireless sensor networks", Springer Verlag. 2006
3.	H.Edgar,Jr.Callaw ay	"Wireless sensor networks, architecture and Protocols", CRC Press. 2004

Course Outcomes: Student will be able to

- **CO1:** Discuss on WSN architecture and technologies.
- **CO2:** Discuss on Wireless sensor platforms.
- **CO3:** Describe the communication architecture and protocols for WSN.
- **CO4:** Discuss on sensor tasking and control.
- **CO5:** Discuss on sensor data acquisition, processing and handling.
- **CO6:** Design the circuit for a particular application using appropriate tool. Prepare the report.

Data Structures using C

Contact Hours/ Week	: 2+0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE43		

Course Objective: Enable students to implement different data structures using C.

UNIT- I

Structures and Unions: Defining a Structure, declaring Structure variables, accessing Structure members, Structure initialization, copying and comparing Structure variables, and operations on individual members, array of Structures, array within Structure, Structure within Structure, Structures and Functions, Unions, size of structures. File management in C: Defining and Opening a file, Closing a file, Input/output operations on files - getc(), putc(), getw(), putw(), fscanf(), fprintf(), Error handling during I/O operations - feof(), ferror(), Random access to files - ftell(), rewind(), fseek(), Command line arguments.

UNIT- II

The Stack: Definition and Examples, representing Stacks in C, Example: Infix, Postfix, and Prefix.

Recursion: Recursive Definition and Processes, Recursion in C.

Queues: The Queue and Its Sequential Representation: C implementation of Queues, Insertion, Deletion and Display operations, Types of Queues (Linear and Circular Queues) Self-Study: Priority and Double Ended Queues.

(05+05) Hrs

UNIT- III

Dynamic memory allocation: malloc(), calloc(), realloc(), free().

Linked lists: Inserting and removing nodes from a list, linked implementation of stacks, getnode and freenode operations, linked implementation of queues, examples of list operation, list implementation of priority queues, header nodes.

Lists in C: allocating and freeing dynamic variables, linked lists using dynamic variables, queues as lists in C, examples of list operations in C, non-integer and non-homogeneous lists, implementing header nodes.

(05+05) Hrs

(06+06) Hrs

UNIT- IV

Other List Structures: Circular lists, stack as a circular list, queue as a circular list, primitive operations on circular lists, doubly linked lists, Primitive operations on doubly linked list.

(05+05) Hrs

UNIT- V

Trees: Operations on Binary Trees, Applications of Binary Trees, and Binary Tree Representations: Node representation of Binary Trees, Internal and External Nodes, Implicit array representation of Binary Trees, Binary Tree Traversals in C. Trees and Their applications: C Representations of Trees, Tree Traversals, General Expressions as Trees, Evaluating an Expression Tree, Constructing a Tree.

(05+05) Hrs

Text Books:

1	Yashavant Kanetkar	Data Structures Through publications, 4 th Edition, 2022.	C,	BPB
2	E. Balagurusamy	Programming in ANSI C, 3 rd Edi 2018.	tion,	ТМН,
3	Yedidyah Langsam, Moshe J. Augenstein, Aaron M. Tenenbaum	Data structures using C and C++ Edition, 2015.	-, PH	I, 2nd

Course outcomes: On successful completion of this course, students will be able to:

CO1: Apply advanced C programming techniques like pointers, structures, union and files to develop solution for a given problem.

CO2: Discuss and implement different linear data structures like stacks and queues using static memory allocation technique.

CO3: Discuss different types of linked lists and implement using dynamic memory allocation technique.

CO4: Discuss non-linear data structures like trees and implement using dynamic memory allocation technique.

CO5: Apply the knowledge of stacks, queues, linked lists and trees to design and develop solutions to given problems.

RISC V Processor Design

Contact Hours/ Week	: 2+0+2(L+P+T)	Credits :	3.0
Total Lecture Hours	: 26	CIE Marks :	50
Total Tutorial Hours	: 26	SEE Marks :	50
Course Code	: N2LVSE44		

Course Objective: To impart the knowledge of RISC-V Instruction Set Architecture and its design.

UNIT-I

Evolution of the RISC-V Architecture: RISC-V Base Instruction Sets and Extensions. Comparison of RISC-V, MIPS, ARM and x86 Architectures, Programmers model for RV32I, Operation and addressing modes of Data Processing instructions, Control transfer instructions, Conditional branches, Assembly level programming examples.

UNIT-II

Data Transfer Instructions, Control and Status Register Instructions, Pseudo Instructions, Assembler directives, RISC-V Machine level instruction formats: Base Instruction formats for R, I, S/B, U/J type instructions, immediate encodings. RISC-V memory map, Compiling, Assembling, Linking and Loading RISC-V programs, Exception handlers. Assembly level programming examples.

(05+05) Hrs

(06+06) Hrs

UNIT-III

RISC-V Microarchitecture design: Architectural state and Instruction set, Design process, Performance analysis, Single cycle processor design: Single cycle data-path and control. Multi-cycle processor design: Multi-cycle datapath and control. Pipelined processor design:

UNIT-IV

HDL representation of Single cycle processor: Controller, Main decoder, ALU decoder, Resettable flip-flop with enable, Data path, Extend unit, Multiplexers, Test bench, Top level module, Instruction memory and data memory.

(05+05) Hrs

UNIT- V

Pipelined processor data-path and control. Hazards, Branch predictions, Super Scalar processors, out-of-order processors, register renaming, Multithreading, Multiprocessors.

(05+05) Hrs

(05+05) Hrs

Text Books:

1	Sarah L Harris David Money Harris	Digital Design and Computer Architecture RISC-V Edition, Morgan Kaufmann Publishers, 2022.	
2	David Patterson, Andrew Waterman	RISC-V Reader: An Open Architecture Atlas, Strawberry Canyon, 1st Edition, 2017	

Reference Books:

1	David A. Patterson	Computer Organization and Design The
	John L. Hennessy	Hardware/Software Interface RISC-V Edition,
		Morgan Kaufmann Publishers, 2020
2	Edson Borin	Introduction to Assembly programming with RISC-V, 1st Edition, 2024, ISBN:978-65-00-15811-3
3	Anthony J Dos Reis	RISC-V Assembly Language, 2019 ISBN-13 : 978-1088462003

Course outcomes: On successful completion of this course, students will be able to:

CO1: Develop Assembly level programs for basic arithmetic and logical operations using RISC-V processor.

CO2: Interpret Assembly level instructions of RISC-V in to its Machine level code.

CO3: Design RISC-V Microarchitectures.

CO4: Develop HDL for different elements of RISC-V design.

CO5: Design pipelined RISC-V processor architecture.